

POLARIZATION MECHANISMS:-

Dielectric polarization is the displacement of charged particle under the action of the external electric field. There are four type of polarization mechanisms as follows.

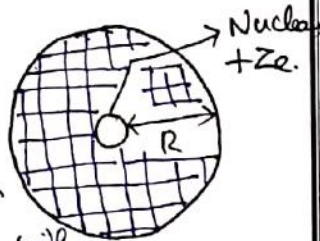
- i) Electronic Polarization
- ii) Ionic Polarization
- iii) Orientation Polarization
- iv) Space-Charge Polarization.

1) Electronic Polarization:-

Electronic polarization occurs due to displacement of the charge nucleus and -ve charge electrons in opposite direction, when an external electric field is applied; they create a dipole moment in the dielectric.

Without Field:

Nucleus '+Ze' is surrounded by electron cloud of charge -Ze with sphere of Radius 'R'.



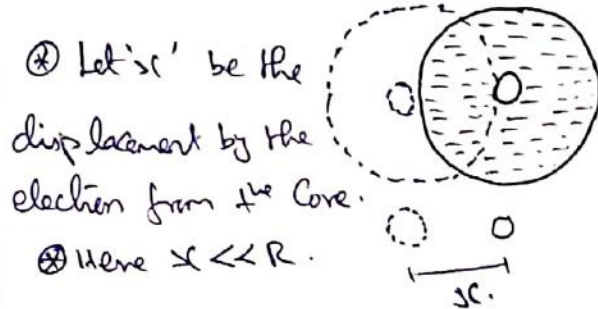
Charge Density of the charged sphere } = $\frac{-Ze}{\frac{4}{3}\pi R^3}$

Charge Density = $-\frac{3}{4} \frac{Ze}{\pi R^3}$ — (1)

With Field:

Two phenomenon are occurs

- i) Lorentz force due to electric field to separate the nucleus and the electron cloud from their equilibrium position
- ii) Coulomb force - attractive force between nucleus and electron cloud.



Lorentz force

Lorentz force = $-ZeE$ — (2)

Coulomb force.

Coulomb force = charge * field.

= $Ze * \frac{Q}{4\pi\epsilon_0 x^2}$ — (3)

Q => Total No. of -ve charge in sphere

∴ Q = Charge Density * Volume of sphere

= $-\frac{3}{4} \frac{Ze}{\pi R^3} * \frac{4}{3} \pi R^3$

∴ Q = $-\frac{Ze R^3}{R^3}$ — (4)

Substitute eqn. (4) in (3)

Coulomb force = $Ze * \frac{-Ze R^3}{4\pi\epsilon_0 x^2 R^3}$

= $-\frac{Z^2 e^2 x}{4\pi\epsilon_0 R^3}$ — (5)

At equilibrium;

Lorentz force = Coulomb force.

$$\therefore -ZeE = -\frac{Z^2 e^2 x}{4\pi\epsilon_0 R^3}$$

$$E = \frac{Ze x}{4\pi\epsilon_0 R^3}$$

Displacement; $x = \frac{4\pi\epsilon_0 R^3 E}{Ze} \rightarrow (6)$

Displacement Directly proportional to Applied Electric field.

When an external electric field is applied to create a dipole moment in the dielectric.

\therefore Induced Dipole moment = Magnitude of charge * Displacement

$$\mu_e = Ze x$$

$$\mu_e = Ze \cdot \frac{4\pi\epsilon_0 R^3 E}{Ze}$$

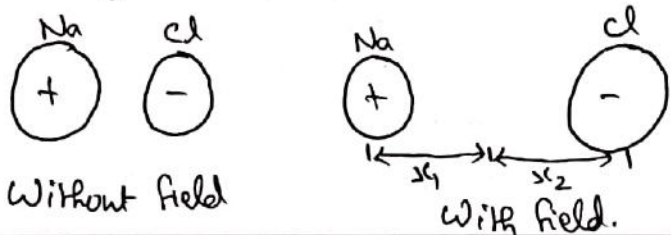
$$\mu_e = 4\pi\epsilon_0 R^3 E \quad \boxed{\mu_e \propto E}$$

ie $\mu_e = \alpha_e E$

$\alpha_e = 4\pi\epsilon_0 R^3$ is called Electronic Polarization which is proportional to volume of sphere.

ii) Ionic Polarization:

Ionic Polarization due to the displacement of cations and anions from its original position.



Let us assume a unit cell of NaCl. During the electric field, ' x_1 ' & ' x_2 ' be the distance moved by the +ve & -ve ions, due this dipole moment is occurs

Induced dipole moment = Magnitude of charge * Displacement

$$\mu_i = e(x_1 + x_2) \rightarrow (1)$$

for +ve ions

for -ve ions

Restoring force, $F \propto x_1$

Restoring force, $F \propto x_2$

$$F = \beta_1 x_1$$

$$F = \beta_2 x_2$$

$$F = m\omega_0^2 x_1$$

$$F = M\omega_0^2 x_2$$

w.k.t.

$$F = eE$$

$$eE = m\omega_0^2 x_1$$

$$eE = M\omega_0^2 x_2$$

$$x_1 = \frac{eE}{m\omega_0^2}$$

$$x_2 = \frac{eE}{M\omega_0^2}$$

Substitute ' x_1 ' & ' x_2 ' in eqn. (1)

$$\mu_i = e \left[\frac{eE}{m\omega_0^2} + \frac{eE}{M\omega_0^2} \right]$$

$$\mu_i = \frac{e^2 E}{\omega_0^2} \left[\frac{1}{m} + \frac{1}{M} \right]$$

$$\mu_i = \alpha_i E$$

$$\therefore \alpha_i = \frac{e^2}{\omega_0^2} \left[\frac{1}{m} + \frac{1}{M} \right]$$

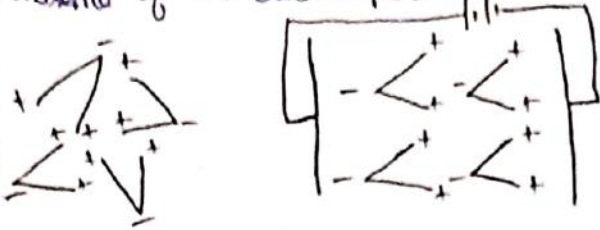
Ionic Polarization

$$\alpha_i \Rightarrow$$

Inversely proportional to square of natural frequency (ω_0^2)
 \Rightarrow Directly proportional to Reduced mass ($\frac{1}{m} + \frac{1}{M}$)

iii) Orientation Polarization :

Polar molecules which have permanent dipole moment even in the absence of an electric field.



Without field

With field.

When the field is applied, positive portion align along the direction of field and negative portion align in the opposite direction of the field. This kind of polarization is called as Orientation Polarization.

⊗ Langevin theory of paramagnetism,

$$\text{Intensity of magnetisation } \int = \frac{N\mu^2 B}{3k_B T}$$

⊗ Same principle applied to application of electric field.

$$\text{Orientation Polarization } \int P_0 = \frac{N\mu^2 E}{3k_B T}$$

$$P_0 = N\alpha_o E$$

$\alpha_o \Rightarrow$ Orientation Polarizability :

$$\alpha_o = \frac{\mu^2}{3k_B T}$$

Inversely proportional to Temperature.

iv) Space-Charge Polarization :

Space-charge polarization occurs due to diffusion of ions, along the field direction and giving rise to redistribution of charges in the dielectrics.



Without field

With field.

Total field - Polarization :

Total Polarizability, $\alpha = \alpha_e + \alpha_i + \alpha_o$

$$\alpha = 4\pi\epsilon_0 R^3 + \frac{e^2}{\omega_0^2} \left(\frac{1}{m} + \frac{1}{M} \right) + \frac{\mu^2}{3k_B T}$$

$$\therefore P = N\alpha E$$

$$\therefore P = NE \left[4\pi\epsilon_0 R^3 + \frac{e^2}{\omega_0^2} \left(\frac{1}{m} + \frac{1}{M} \right) + \frac{\mu^2}{3k_B T} \right]$$

This equation is called

"Langevin-Debye Equation"

INTERNAL FIELD (OR) LOCAL FIELD

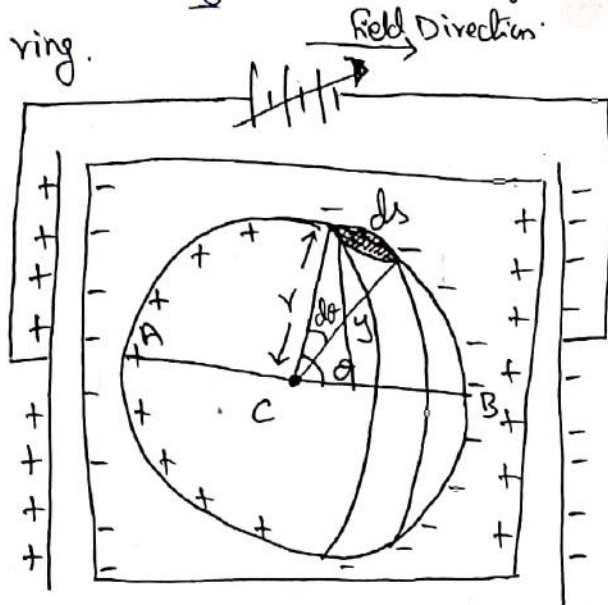
CLAUSIUS - MOSOTTI EQN. :-

Long range of Coulomb force which is created due to the dipoles are called Internal field, it is responsible for polarizing individual atom or molecules

Let us assume a dielectric material kept in an electric field, Consider an imaginary sphere of radius ' r ' is greater than the radius of atoms.

A small elemental ring is cut with thickness ' ds '.

Let ' y ' be the radius of small ring.



The electric field at the Centre of the Sphere is called "Internal field".

$$E_{int} = E_1 + E_2 + E_3 + E_4 \longrightarrow \textcircled{1}$$

$E_1 \Rightarrow$ field due to charge on the plate.

$E_2 \Rightarrow$ field due to polarized charge on the plane surface of dielectric

$E_3 \Rightarrow$ field due to polarized charge induced at the spherical surface.

$E_4 \Rightarrow$ field due to atomic dipole inside the Sphere Considered.

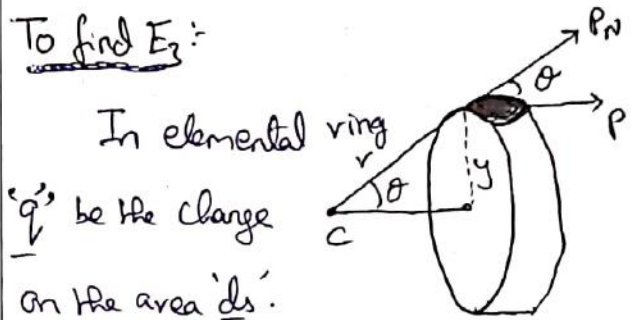
Here.

$$E = E_1 + E_2$$

$$E_4 = 0$$

$$\therefore E_{int} = E + E_3 \longrightarrow \textcircled{2}$$

To find E_3 :



Polarization, $P_N = \frac{\text{Surface Area charge}}{\text{Area}}$

$$P_N = q' / ds = P \cos \theta$$

$$q' = P \cos \theta ds$$

$$\therefore \text{Electric field intensity at 'C' due to } q' \} E = \frac{q'}{4\pi\epsilon_0 r^2}$$

$$E = \frac{P \cos \theta ds}{4\pi\epsilon_0 r^2} \longrightarrow \textcircled{1}$$

Resolving the intensity into two Component

Parallel; $E_s = E \cos \theta$

$$\therefore E_s = \frac{P \cos^2 \theta ds}{4\pi\epsilon_0 r^2}$$

Perpendicular; $E_y = E \sin \theta$

$$\therefore E_y = \frac{P \cos \theta \sin \theta ds}{4\pi\epsilon_0 r^2}$$

* The \perp Component are in opposite direction & cancel to each other.

* Total surface area of elemental ring is " ds ".

$$E_r = E = \frac{P \cos^2 \theta dA}{4\pi \epsilon_0 r^2}$$

$$dA = \text{Circumference} \times \text{Thickness.}$$

$$= 2\pi r \times ds$$

$$dA = 2\pi r \sin \theta \times r d\theta$$

$$dA = 2\pi r^2 \sin \theta d\theta$$



$$\left. \begin{array}{l} \text{Electric field} \\ \text{Intensity due to} \\ \text{Elemental ring} \end{array} \right\} = \frac{P \cos^2 \theta \sin \theta d\theta}{2\epsilon_0}$$

$$\left. \begin{array}{l} \text{Electric field Intensity} \\ \text{whole sphere} \end{array} \right\} E_3 = \int_0^\pi \frac{P \cos^2 \theta \sin \theta d\theta}{2\epsilon_0}$$

$$E_3 = \frac{2}{3} \left(\frac{P}{2\epsilon_0} \right)$$

$$E_3 = \frac{P}{3\epsilon_0}$$

$$\therefore E_{int} = E + \frac{P}{3\epsilon_0}$$

CLAUSIUS - MOSSOTTI RELATION:

w.k.T.

$$D = \epsilon E = \epsilon_0 E + P$$

$$P = E(\epsilon - \epsilon_0)$$

$$E = \frac{P}{\epsilon - \epsilon_0}$$

$$\therefore E_{int} = \frac{P}{\epsilon - \epsilon_0} + \frac{P}{3\epsilon_0}$$

$$E_{int} = \frac{P(2\epsilon_0 + \epsilon)}{3\epsilon_0(\epsilon - \epsilon_0)}$$

$$P = N\alpha E_i$$

$$\therefore E_{int} = \frac{P}{N\alpha}$$

$$\frac{P}{N\alpha} = \frac{P(2\epsilon_0 + \epsilon)}{3\epsilon_0(\epsilon - \epsilon_0)}$$

$$\frac{N\alpha}{3\epsilon_0} = \frac{\epsilon - \epsilon_0}{2\epsilon_0 + \epsilon}$$

$$\frac{N\alpha}{3\epsilon_0} = \frac{\epsilon_r - 1}{\epsilon_r + 2}$$

CLAUSIUS - MOSSOTTI RELATION.

GAUSS' LAW:

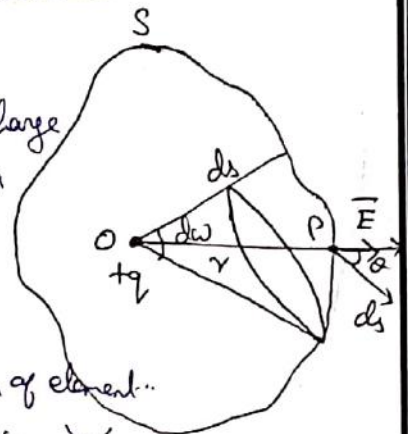
The total Electric flux " ϕ " in any closed surface is equal to $\frac{1}{\epsilon_0}$ times the total charge enclosed by the surface.

$$\therefore \phi = \oint_S E ds$$

$$\phi = \frac{\Sigma q}{\epsilon_0}$$

Electric charge situated inside closed surface:-

Let a point charge '+q' is placed at a point 'O' inside a closed surface 'S'.



$ds \Rightarrow$ Small area of element at a distance 'r' from 'q'.

E is electric field normal to this surface is $E \cos \theta$.

$$\text{Electric flux } d\phi = \vec{E} \cdot d\vec{s} \rightarrow \text{①}$$

Surface

$$d\phi = E \cos\theta \, ds \longrightarrow \textcircled{2}$$

$\theta \Rightarrow$ Angle between \vec{E} & \vec{ds} .

Electric field at 'P' due to q } $E = \frac{q}{4\pi\epsilon_0 r^2} \longrightarrow \textcircled{3}$

$$d\phi = \frac{q}{4\pi\epsilon_0 r^2} [\cos\theta \, ds]$$

$$d\phi = \frac{q}{4\pi\epsilon_0} d\omega \quad \because d\omega = \frac{ds \cos\theta}{r^2}$$

Total flux } $\phi = \frac{q}{4\pi\epsilon_0} \oint d\omega$
 Entire surface } $= \frac{q}{4\pi\epsilon_0} 4\pi$

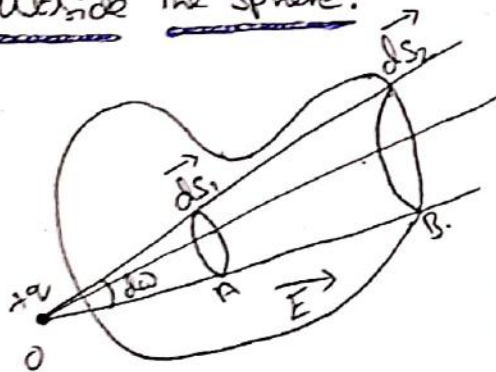
$$\therefore \phi = \frac{q}{\epsilon_0}$$

If there are several charges q_1, q_2, q_3 inside the surface.

$$\therefore \text{Total flux; } \phi = \frac{1}{\epsilon_0} \sum q$$

$$\therefore \phi = \frac{1}{\epsilon_0} \sum q = \oint \vec{E} \cdot d\vec{s}$$

Charge outside the Sphere:-



Let the charge $+q$ be situated outside the closed surface at point 'O'.

Let " $d\omega$ " be small solid angle for elementary cone, cut two element of closed surface " dS_1 " & " dS_2 " at A & B.

Magnitude of flux through " dS_1 " and " dS_2 " are equal.

Flux through " dS_1 " is inward while " dS_2 " is outward flux.

$$\therefore \text{Total flux} = \frac{-q}{4\pi\epsilon_0} d\omega + \frac{q}{4\pi\epsilon_0} d\omega = 0$$

"Total flux due to a charge outside is zero."

INSULATION BREAKDOWN IN SOLID, LIQUIDS & GASES:-

$$\text{Dielectric strength} = \frac{\text{Breakdown voltages}}{\text{Thickness of Dielectric}}$$

When the strength of electric field applied to a dielectric exceed a critical value, very large current flow through it. The dielectric loses its insulating property and becomes a conductor. This phenomenon is called 'Dielectric Breakdown'.

Breakdown in Gaseous Dielectric:-

⊗ It occurs due to ionization caused by collision of electrons. When a strong electric field is applied the accelerated free electrons act with energy greater than the ionization of the gas.

⊗ It depends on pressure, applied electric field, polarity of electrodes, frequency of applied field.

Breakdown in Liquids:-

The impurities in a liquid have small conductive particles, they create conductive bridges between the electrodes. This leads to discharge.

Breakdown in Solid:-

There are various major mechanisms that lead to dielectric breakdown in solids. Some of the dielectric breakdown in solids are:

i) Intrinsic Breakdown:-

When the electric field is applied, the valence band acquires sufficient energy and goes to the conduction band by crossing the energy gap and hence

becomes conducting. Electron current flows and is called Intrinsic Breakdown or Zener Breakdown.

Avalanche Breakdown:-

Secondary conduction electrons again dislodge some other bound electrons in the valence band and this process continues as a chain reaction. Therefore, very large current flows through the dielectric and hence called as "Avalanche Breakdown".

ii) Thermal Breakdown:-

When a dielectric is subjected to an electric field, heat is generated. The temperature inside the dielectric increases and heat may produce breakdown. This type of breakdown is known as Thermal Breakdown.

iii) Chemical & Electrochemical Breakdown.

When the mobility of ions increases, insulation resistance decreases and hence dielectric becomes conducting. This type of breakdown is called as Chemical (or) Electrochemical Breakdown.

iv) Discharge Breakdown

The gas present in the material will easily ionize and hence produce large ionization current known as Discharge Breakdown.

v) Defect Breakdown:-

Some dielectric have defect such as cracks, pores, blow holes etc. These vacant position may have moisture or impurities which leads to breakdown called as "Defect Breakdown".

PIEZOELECTRICITY & CRYSTAL

Piezoelectricity:-

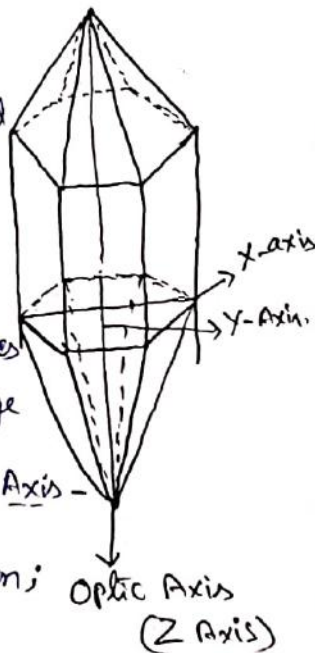
When mechanical stress is applied on dipolar crystal; electricity is produced due to the displacement of dipole. This phenomenon is called "piezoelectricity".

The crystal which produce piezo-electric effect and converse piezo-electric effect are termed as "piezo-electric crystal".
Eg. Quartz, Tourmaline, Topaz.

Quartz Crystal:-

It has a hexagonal shape with pyramid attached at both ends.

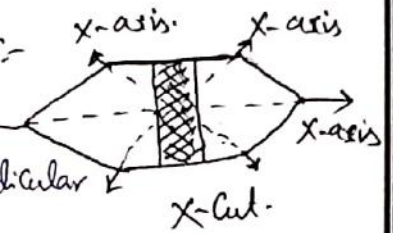
It consist of 3 axes
Optic axis:- joins the edge of pyramids;
Electrical Axis:- join the corner of hexagon;
Optic Axis (Z Axis)



Mechanical axis - join the centre side of the hexagon.

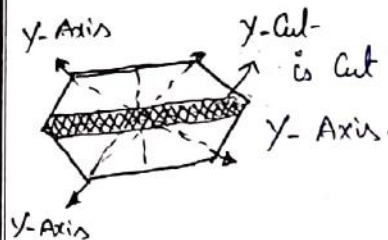
X-Cut Crystal:-

When the crystal is perpendicular to the X-axis.



Y-Cut Crystal:-

When the crystal is cut perpendicular to Y-Axis.



⊗ When pressure (or) mechanical force is applied along certain axis (Mechanical Axis) w.r.t. optic axis of the crystal, then equal and opposite charges are produced along perpendicular axis (Electrical axis) w.r.t. optic axis of the crystal. This effect is called "piezoelectric Effect".

⊗ When potential difference is applied along ++++++



Certain axis (Electrical Axis) w.r.t. optic axis of the piezoelectric crystal then the crystal starts vibrate along the Y axis (Mechanical). This effect is called "Inverse Piezoelectric Effect".

Properties:

- ⊗ Piezoelectricity phenomenon exists due to crystal anisotropy.
- ⊗ Piezoelectricity have linear effect, where as ferroelectricity has non-linear effects.

Application:

- ⊗ Piezoelectric crystal are used in microphones, ultrasonic devices, sonar detector etc.
- ⊗ It act as a transducer and is used to generate ultrasonic waves.

PYROELECTRICITY IN CRYSTAL :-

Some piezoelectric crystals when heated, then it produces electricity to a small extent and this phenomenon is called Pyroelectricity. The crystal that exhibit this phenomenon are called Pyroelectric crystals.

Eg. Tourmaline, Gallium nitride, Lithium tantalate.

Properties:

- ⊗ Pyro electric crystal will have unidirectional polarization.
- ⊗ The crystals are Non-Centrosymmetric in nature

Applications:

- ⊗ Pyroelectric crystal are used in IR detector, elements
- ⊗ These are also used in temperature sensors.

FERRO ELECTRIC MATERIALS :-Ferro-Electricity:

When a dielectric material exhibits electric polarisation even in the absence of external field, it is known as "ferro-Electricity", these materials are termed as "ferro-Electric".

Properties:

- ⊗ Ferro-electric material also exhibits hysteresis, similar to that of ferro-magnetic materials
- ⊗ They exhibits domain structure similar to that of ferro-magnetic material.
- ⊗ ferro-electric material also exhibits hysteresis, electric polarisation very easily, even in the absence of external electric field.

Application :-

- ⊗ ferro-electric material are used to produce ultrasonics.

④ Ferro-electric are also used in SONAR, strain gauges etc

⑤ They are also used as frequency stabilizers and crystal controlled oscillator.

⑥ Used to produce high sensitive infra-red detectors.

CAPACITOR MATERIALS - TYPICAL

CAPACITOR CONSTRUCTION:

Dielectric material are used to manufacture capacitor of different ranges.

Dielectric material such as paper and plastic film, mica film, single layer ceramic, multilayer ceramic, solid electrolytic are used in capacitor.

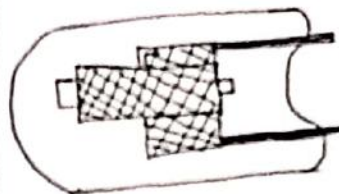
1. Single & Multilayer Capacitors:

The diagrammatic representation of a single layer capacitor. It consist of thin ceramic disk or plate placed in between the metal electrodes. The leads for the electrical connection, are taken from the metal electrode.

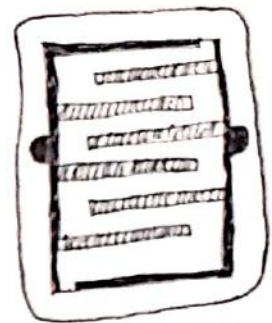
In order to prevent the

degradation of dielectric ceramic plate it is encapsulated in an epoxy coating.

The capacitance of single layer capacitor for an area, is the capacitance of the capacitor by connecting N number of ceramic plate in parallel providing a sufficient space.



SINGLE LAYER
Ceramic Capacitor



MULTI LAYER
Ceramic Capacitor

The capacitor with stacking of ceramic plate in different layer is known as "Multi-layer capacitor". The capacitance of multi-layer capacitor is in the range of few hundred microfarads.

2. Polymeric film capacitors:

Polymer thin film capacitor are mid-frequency capacitor. The two metal coated polymer film are placed in parallel.

The electrical connection are taken opposite side of metal by proper soldering.

3. Paper Capacitors :-

A long strip of paraffin waxed paper is kept in between the coating of tin (or) aluminium foil and rolled into a cylinder.



The strips are tightly rolled and the whole capacitor is dipped in paraffin.

The tin or aluminium foils with the dielectric are rolled as soon to occupy a very small space.

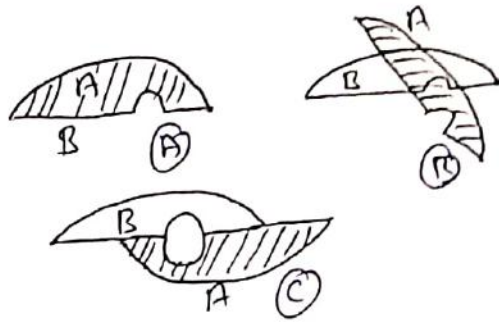
Paraffin waxed paper the thickness of the dielectric is very small and hence the capacity of the capacitor is very high.

These capacitor are very cheap. The dielectric constant of paper is about 3.5. These are suitable in audio frequency circuits as by-pass or coupling capacitors.

4. Variable Air Capacitor :-

Capacitor is commonly used in wireless set and electronic circuits.

It consist of two set of aluminium plate. One set of plate 'A' is fixed, other set of plate can be rotated 'B' by a knob attached to it.



Show the variation in the area of overlap between the plate A & B

Corresponds the maximum capacity where the set of plate overlap each other. Fig. "A"

Corresponds to the minimum capacity where the rotating plate are completely rotated out of fixed plate. Fig. "C"

Expression for the Electrical Conductivity:

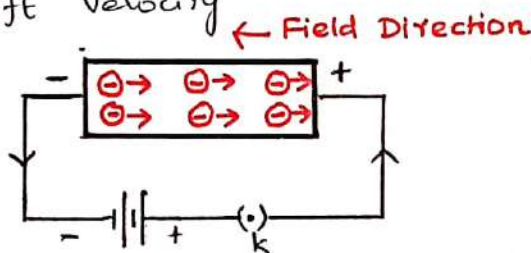
Definition:-

It is the quantity of Electric charges flowing per unit time (t) per unit area (A) maintained at a unit potential gradient (E).

$$\sigma = \frac{Q}{tAE} = \frac{ne^2\tau}{m^*} \quad \text{m}^{-1}\text{m}^{-1}$$

Derivation:

When an electrical field applied to an electron of charge 'e', it moves in a opposite direction with the applied field with a constant velocity (v_d) known as "drift velocity"



Here the force experienced by the electron by external field

$$F = eE \quad \text{--- (1)}$$

and the acceleration gained by the electron 'a' is given by

$$\text{acceleration } a = \frac{\text{velocity}}{\text{Time}} = \frac{v_d}{\tau}$$

$$\therefore a = \frac{v_d}{\tau}$$

$$v_d = a\tau \quad \text{--- (2)}$$

We know that from Newton's II law,

$$F = ma \quad \text{--- (3)}$$

By comparing eqns (1) & (3)

$$eE = ma$$

$$a = \frac{eE}{m} \quad \text{--- (4)}$$

Substituting eqn (4) in eqn (2)

$$v_d = \frac{eE\tau}{m} \quad \text{--- (5)}$$

If $n \rightarrow$ no. of free electron
 $e \rightarrow$ charge of an electron

Then current density in terms of

v_d is given by

$$J = nev_d \quad \text{--- (6)}$$

Substitute eqn (5) in eqn (6)

$$J = ne \frac{eE\tau}{m}$$

$$J = \frac{ne^2E\tau}{m} \quad \text{--- (7)}$$

From the definition of Charge density is directly proportional to applied electric field.

$$J \propto E$$

$$J = \sigma E \quad \text{--- (8)}$$

Comparing eqns (7) & (8) we get

$$\sigma E = \frac{ne^2\tau E}{m}$$

$$\sigma = \frac{ne^2\tau}{m} \quad \text{--- (9)}$$

Eqn (9) is the expression for the electrical conductivity.

Thermal Conductivity:

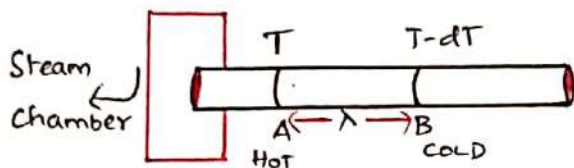
Definition:

It is the amount of heat conducted per unit area (A), per unit time (t) maintained at unit temperature gradient.

$$k = \frac{Q}{dT/dx} = \frac{n v^2 k_B \tau}{2}$$

Derivation:-

Consider a uniform metallic rod contain free electron.



Here A & B → cross-sectional area near hot & cold end

T, T-dT → Temp at A & B.

λ → Mean free path.

The average K.E of electrons crossing A

$$E_1 = \frac{1}{2} m v^2 = \frac{3}{2} k_B T \quad \text{--- (1)}$$

Similarly K.E of free electron at 'B'

$$E_2 = \frac{3}{2} k_B (T-dT) \quad \text{--- (2)}$$

Excess energy carried out by electrons from A to B

$$\begin{aligned} \text{K.E} &= \frac{3}{2} k_B T - \frac{3}{2} k_B (T-dT) \\ &= \frac{3}{2} k_B T - \frac{3}{2} k_B T + \frac{3}{2} k_B dT \end{aligned}$$

$$\text{K.E} = \frac{3}{2} k_B dT \quad \text{--- (3)}$$

Assume, the electron can move in all possible direction, then the no. of electron crossing per unit area, per unit time from 'A' to 'B'.

$$n = \frac{1}{6} n v \quad \text{--- (4)}$$

∴ The excess average energy carried from A to B is given by

$$E = \frac{1}{6} n v \times \frac{3}{2} k_B dT$$

$$E = \frac{1}{4} n v k_B dT \quad \text{--- (5)}$$

Hence the net amount of heat transformed from 'A' to 'B'.

$$Q = \frac{1}{4} n v k_B dT - \left[-\frac{1}{4} n v k_B dT \right]$$

$$Q = \frac{1}{2} n v k_B dT \quad \text{--- (6)}$$

from the definition, we know that

$$Q = k \cdot \frac{dT}{dx}$$

$$Q = k \cdot \frac{dT}{\lambda} \quad \text{--- (7)}$$

By comparing eqn (7) & (6)

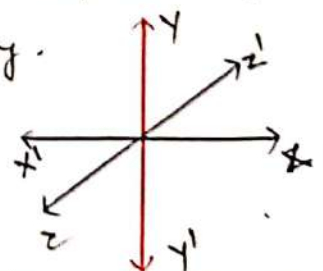
$$k \frac{dT}{\lambda} = \frac{1}{2} n v k_B dT$$

$$k = \frac{1}{2} n v k_B \lambda \quad \text{--- (8)}$$

Wkt λ = vτ

$$\therefore k = \frac{1}{2} n v^2 k_B \tau \quad \text{--- (9)}$$

Eqn (9) is the expression for thermal conductivity.



Fermi Distribution function:-

Definition:

It is the probability of occupation of electrons among different energy levels at absolute temperature.

It is given by

$$F(E) = \frac{1}{1 + e^{(E-E_F)/k_B T}}$$

where $E \rightarrow$ Energy level to be considered.

$E_F \rightarrow$ Fermi energy level.

$k_B \rightarrow$ Boltzmann Constant

$T \rightarrow$ Absolute Temperature.

If $F(E) = 1$, the energy level is occupied by an electron.

If $F(E) = 0$, the energy level is vacant

If $F(E) = 0.5$, then there is 50% chance for the electron to occupy.

Case (i)

If $E < E_F$ at $T = 0K$

$$\begin{aligned} \text{Then } F(E) &= \frac{1}{1 + e^{(E-E_F)/k_B T}} \\ &= \frac{1}{1 + e^{(E-E_F)/0}} \\ &= \frac{1}{1 + e^{-\infty}} = \frac{1}{1+0} = 1 \end{aligned}$$

$$F(E) = 1$$

Thus at $T = 0K$, 100% chance for the electrons to occupy the energy levels.

Case (ii)

If $T = 0K$ at $E > E_F$

$$\begin{aligned} \text{Then } F(E) &= \frac{1}{1 + e^{(E-E_F)/k_B T}} \\ &= \frac{1}{1 + e^{\infty}} = \frac{1}{1+\infty} \end{aligned}$$

$$F(E) = 0$$

Thus 0% chance for the electron to occupy the energy levels

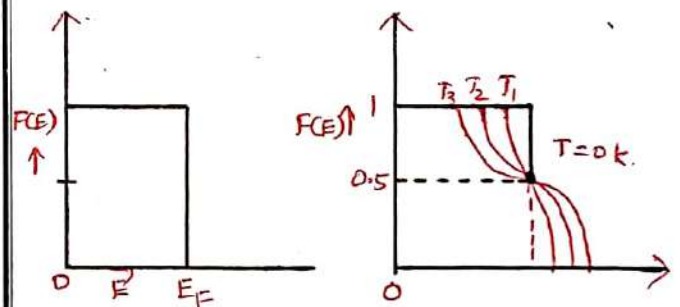
Case (iii)

If $T > 0K$ at $E = E_F$

$$F(E) = \frac{1}{1 + e^0} = \frac{1}{1+1}$$

$$F(E) = \frac{1}{2} \quad \text{or} \quad F(E) = 0.5$$

There is 50% chance for the electrons to occupy the fermi energy level



Variation of E_F with respect to temperature.

When $T = 0K$, occupation is upto E_F

When $T > 0K$ valence electrons got breakdown in its bond and exited to conduction band.

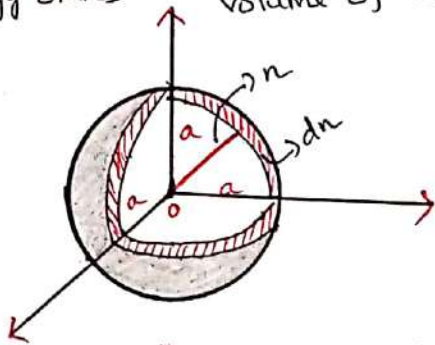
Density of Energy States:-

Definition:

It is defined as the no. of available energy states presented per unit volume of a metal piece.

$$N(E)dE = \frac{N(E)dE}{V}$$

Density of Energy States = $\frac{\text{No. of available energy state between } E \text{ \& } E+dE}{\text{Volume of a metal.}}$



Let us consider a sphere inside a cubical metal piece of side 'a'.

* Here n_x, n_y, n_z are the coordinate axes.

* $n \rightarrow$ inner radius of the sphere.

* E and $E+dE$ are the energy of the inner and outer shell of the sphere.

- * The sphere consists of no. of shells, between inner and outer shell each represents a energy level.

The no of available energy states within the thickness of the sphere of radius 'n'

$$n = \frac{1}{8} \left[\frac{4\pi n^3}{3} \right] \quad \text{--- (1)}$$

Similarly the energy states within the sphere of radius $(n+dn)$

$$n+dn = \frac{1}{8} \left[\frac{4}{3} \pi (n+dn)^3 \right] \quad \text{--- (2)}$$

Hence, the no. of available energy states between $(n \text{ \& } n+dn)$ the energy interval E and $E+dE$.

$$N(E)dE = \frac{1}{8} \left[\frac{4}{3} \pi (n+dn)^3 - \frac{4}{3} \pi n^3 \right]$$

$$= \frac{1}{8} \left[\frac{4}{3} \pi (n^3 + 3n^2dn + 3ndn^2 + dn^3) \right]$$

$$N(E)dE = \frac{1}{8} \left[\frac{4}{3} \pi (3n^2dn + 3ndn^2 + dn^3) \right]$$

$\because dn$ very small, neglecting the higher orders,

$$N(E)dE = \frac{1}{8} \left[\frac{4}{3} \pi (3n^2dn) \right]$$

$$N(E)dE = \frac{\pi}{2} n^2 dn \quad \text{--- (3)}$$

We know that

the energy of an electron in a cubical metal piece. of side 'a' is

$$E = \frac{n^2 h^2}{8ma^2} \quad \text{--- (4)}$$

Differentiating eqn (4) we have

$$dE = \frac{2n dn \cdot h^2}{8ma^2}$$

$$(i) \quad n dn = \frac{8ma^2}{2h^2} \cdot dE \quad \text{--- (5)}$$

From eqn (4)

$$n^2 = \frac{8ma^2 E}{h^2}$$

$$n = \left[\frac{8ma^2 E}{h^2} \right]^{1/2} \quad \text{--- (6)}$$

Hence eqn (3) can be written as

$$N(E)dE = \frac{\pi}{2} n \cdot n dn \quad \text{--- (7)}$$

By substituting eqn (5) & (6) in (7)

$$N(E)dE = \frac{\pi}{2} \left[\frac{(8m)^{1/2} a^3 E^{1/2}}{h} \right] \left[\frac{8ma^2 dE}{2h^2} \right]$$

$$\therefore N(E)dE = \frac{\pi}{2} \frac{(8m)^{3/2} a^3 E^{1/2} dE}{2h^3} \quad \text{--- (8)}$$

Here $a^3 = V \rightarrow$ volume

\therefore Density of energy states

$$Z(E)dE = \frac{N(E)dE}{V}$$

$$Z(E)dE = \frac{\pi (8m)^{3/2} V E^{1/2} dE}{4h^3 \cdot V}$$

$$Z(E)dE = \frac{\pi}{4h^3} (8m)^{3/2} E^{1/2} dE \quad \text{--- (9)}$$

According to Pauli's exclusion principle in each state 2 electrons can be accommodated.

$$\therefore Z(E)dE = 2 \times N(E)dE$$

$$\therefore Z(E)dE = 2 \times \frac{\pi}{4h^3} (8m)^{3/2} E^{1/2} dE$$

$$Z(E)dE = \frac{\pi}{2h^3} (8m)^{3/2} E^{1/2} dE \quad \text{--- (10)}$$

Carrier Concentration in Metals:

The no. of electrons per unit volume in a given energy interval is calculated by

$$n_c = \int Z(E) F(E) dE \quad \text{--- (11)}$$

We know that

$$Z(E)dE = \frac{\pi}{2h^3} (8m)^{3/2} E^{1/2} dE$$

$$= \frac{\pi}{2h^3} (8)^{3/2} (m)^{3/2} E^{1/2} dE$$

$$= \frac{\pi}{2h^3} (4)^{3/2} \cdot (2)^{3/2} \cdot (m)^{3/2} E^{1/2} dE$$

$$= \frac{\pi}{2h^3} 2^3 \cdot (2m)^{3/2} E^{1/2} dE$$

$$Z(E)dE = \frac{4\pi}{h^3} (2m)^{3/2} E^{1/2} dE \quad \text{--- (12)}$$

$F(E) = 1$ for energy levels $E = 0$ to $E = E_{F0}$

Then eqn (11) becomes

$$n_c = \frac{4\pi}{h^3} (2m)^{3/2} \int_0^{E_{F0}} E^{1/2} dE$$

$$n_c = \frac{4\pi}{h^3} (2m)^{3/2} \left[\frac{E^{3/2}}{3/2} \right]_0^{E_{F0}}$$

$$= \frac{4\pi}{h^3} (2m)^{3/2} \cdot \frac{2}{3} [E_{F0}]^{3/2}$$

$$n_c = \frac{8\pi}{3h^3} (2m E_{F0})^{3/2} \quad \text{--- (13)}$$

Fermi Energy:-

From eqn (13), we know that the carrier concentration n_c can be written as

$$n_c = \frac{8\pi}{3h^3} (2m)^{3/2} (E_{F0})^{3/2}$$

$$\frac{3n_c}{8\pi} \frac{h^3}{(2m)^{3/2}} = [E_{F0}]^{3/2}$$

By raising power on both sides

$$\text{by } 2/3 \quad E_{F0} = \left[\frac{3n_c}{8\pi} \frac{h^3}{(2m)^{3/2}} \right]^{2/3}$$

$$E_{F0} = \left[\frac{3n_c}{8\pi} \right]^{2/3} \left[\frac{h^2}{2m} \right] \quad \text{--- (14)}$$

Effective Mass of Electron:-

Definition:-

The mass acquired by an electron, when it is accelerated in a periodic potential is called effective mass (m^*)

Derivation:-

Consider a crystal subjected to electric field (E). Then the velocity gained by the electrons (v) is described by the wave vector (k) & it is equivalent to the wave packet moving with a group velocity (v_g).

$$v_g = \frac{d\omega}{dk} \quad \text{--- (1)}$$

where $\omega \rightarrow$ angular velocity ($2\pi\nu$)
 $k \rightarrow$ wave vector

We know that

$$E = h\nu \quad \text{(or) } \omega = 2\pi\nu$$

$$\nu = \frac{\omega}{2\pi}$$

$$E = \frac{h\omega}{2\pi}$$

$$E = \hbar\omega \quad \hbar = \frac{h}{2\pi}$$

$$\omega = \frac{E}{\hbar} \quad \text{--- (2)}$$

\therefore Eqn (1) can be written as

$$v_g = \frac{d}{dk} \left[\frac{E}{\hbar} \right]$$

$$v_g = \frac{1}{\hbar} \left[\frac{dE}{dk} \right] \quad \text{--- (3)}$$

Under this condition the acceleration a' of an electron

$$a = \frac{dv_g}{dt}$$

$$= \frac{d}{dt} \left[\frac{1}{\hbar} \left(\frac{dE}{dk} \right) \right]$$

$$a = \frac{1}{\hbar} \frac{d^2E}{dk^2} \cdot \frac{dk}{dt} \quad \text{--- (4)}$$

The momentum of an electron from de-Broglie wave length

$$p = \frac{h}{\lambda}$$

$$p = \frac{h}{2\pi} \cdot \frac{2\pi}{\lambda}$$

$$p = \hbar \frac{2\pi}{\lambda}$$

$$p = \hbar k \quad \text{--- (5)}$$

Differentiate eqn (5) w.r.t. 't'

$$\frac{dp}{dt} = \hbar \frac{dk}{dt} \quad \text{(or) } \frac{dk}{dt} = \frac{F}{\hbar} \quad \text{--- (6)}$$

[Force acting on the electron $F = \frac{dp}{dt}$]

Hence eqn (4) can be written as

$$a = \frac{1}{\hbar} \cdot \frac{d^2E}{dk^2} \cdot \frac{F}{\hbar}$$

$$a = \frac{F}{\hbar^2} \frac{d^2E}{dk^2}$$

$$F = \left[\frac{\hbar^2}{\left(\frac{d^2E}{dk^2} \right)} \right] a \quad \text{--- (7)}$$

When an electric field is applied, acceleration of the electron due to field.

$$a = \frac{eE}{m^*} = \frac{F}{m^*}$$

$$F = m^* a \quad \text{--- (8)}$$

Comparing eqns (7) & (8)

$$m^* a = \left[\frac{\hbar^2}{\left(\frac{d^2E}{dk^2} \right)} \right] a$$

$$m^* = \frac{\hbar^2}{\left(\frac{d^2E}{dk^2}\right)} \quad (9)$$

Eqn (9) → Effective mass of an electron is not constant, but depends on the value $\frac{d^2E}{dk^2}$

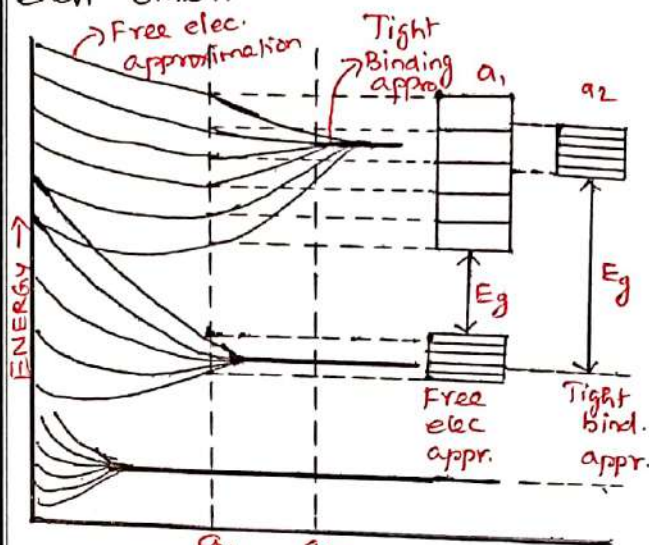
Case (i): $\frac{d^2E}{dk^2} = +ve$, $m^* = +ve$

Case (ii) $\frac{d^2E}{dk^2} = -ve$, $m^* = -ve$

Case (iii) $\frac{d^2E}{dk^2} \rightarrow \text{more}$, m^* is ^{lesser} higher

Case (iii) $\frac{d^2E}{dk^2} \rightarrow \text{less}$, m^* is ^{large} less

* As the atoms are closer to each other, the inter atomic distance decreases and hence the wave functions overlap with each other.



Tight binding approximation:-

Instead of beginning with the solid core, we begin with the electrons, (e) all the electrons are bounded to the atoms. In other words, atoms are free while the electrons are tightly bounded. This is called tight bound approximation.

In tight binding approximation:

- * The P.E of the electrons is nearly equal to the total energy
- * The width of the forbidden bands (E_g) are larger than the allowed bands.
- * Therefore the interactions between the neighbouring atom will be weak.
- * As the atoms are not closer, the inter atomic distance increases and hence the wave functions will not overlap.

Tight Binding Approximation:-

Before discussing about the tight binding approximation, let us know about free electron approximation.


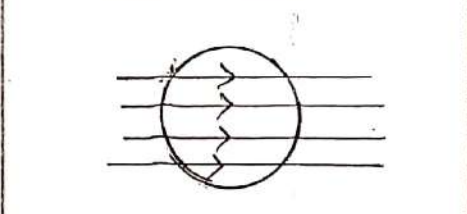
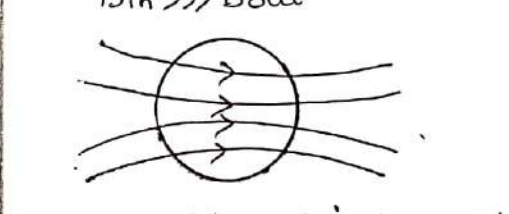
Free electron approximation:-

In solids, ionic core which are tightly bounded to lattice location exists. The electrons are free to move throughout the solid. This is called the free electron approximation.

In free electron approximation,

- * The P.E of the e^- is assumed to be lesser than its total energy.
- * The width of the band gap (E_g) are smaller than the allowed band. (fig)
- * The interaction between the neighbouring atoms will be very strong.

Dia, Para, Ferro Magnetic Effects.

Dia	Para	Ferro
(i) It is non-magnetic material consists of no-permanent dipoles	Temporary magnetic material, consists of permanent dipole.	Permanent magnetic material. Consists of large no. of permanent dipoles.
(ii) Dipoles are opposite to each other in the absence of external field. Net dipole moment is zero	Dipoles are randomly oriented in the absence of external field. Net dipole moment is minimum.	Dipoles are oriented parallel to each other, in the absence of external field. Net dipole moment is large.
(iii) In the presence of external field dipoles align opposite to the external field.	In the presence of external field dipoles align parallel to the external field.	Here also, dipoles align parallel to the external field.
(iv) Magnetic flux lines are repelled out of the material.	Magnetic flux lines are attracted by the material	Magnetic flux lines are attracted maximum by the material.
<p>$B_{in} \ll B_{out}$</p> 	<p>$B_{in} \gg B_{out}$</p> 	<p>$B_{in} \gg \gg B_{out}$</p> 
(v) Permeability (μ) is less than 1 and susceptibility is -ve $\mu < 1, \chi = -ve$	Permeability (μ) is greater than 1 & susceptibility is +ve. $\mu > 1, \chi = +ve$	Permeability (μ) is very much greater than 1, susceptibility is +ve, $\mu \gg 1, \chi = +ve$
(vi) Independent on temperature	Dependent on temperature	Dependent on temperature
(vii) At very low temp. it will be in diamagnetic	Temp above maximum para mag. converted into Dia mag. is known as Curie Temp.	Above Curie temperature it is converted into para materials
Ex: Bismuth, Gold,	Ex: Al, Pt.	Ex: Fe, Ni, Co.

Paramagnetism in the Conduction Electrons in metals

According to Langevin's theory the paramagnetic susceptibility is inversely proportional to the temperature.

$$\chi \propto \frac{1}{T}$$

But in some metals susceptibility is independent of temperature.

Pauli explains that this is due to the free electrons, can orient only in two directions, either along the magnetic field or against it.

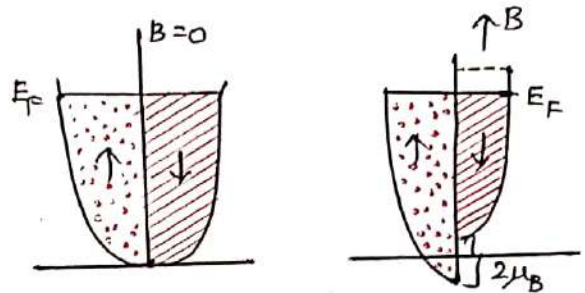
Consider a curve between density of states versus energy at absolute zero of temperature. In this curve there are two parts, one have electron spin along z-direction and another have electron spin opposite to z direction.

In the absence of external field the distribution of electrons in the two parts are equal.

∴ Net mag. moment of the electron gas is zero.

When a mag. field (B) is applied along z-direction, the energy of the spins aligned parallel to B is lowered by the amount μ_B

while the energy of the spins opposite to B is raised by the same amount.



As a result, the Fermi level of the two spin distributions shift with respect to each other and energetically unstable situation.

In order to acquire stable configurations, the e's lying near the Fermi level with antiparallel spins flip into the region of parallel spins until the two Fermi levels become equal again.

No. of electrons which change their direction

$$N_{\text{eff}} = \frac{1}{2} Z(E_F) \mu_B B$$

where $Z(E_F) \rightarrow$ Density of states

$\mu_B \rightarrow$ mag. moment of electron.

The factor $\frac{1}{2}$ is due to the fact that the density of states of one spin distribution is half of the total density of the states.

∴ After application of the field

No. of electrons with spin parallel } No. of electron with spin anti-parallel.

Since each flip increases the magnetisation by $2\mu_B$ (from $-\mu_B$ to $+\mu_B$), the net magnetisation is given by

$$M \approx N_{\text{eff}} \times 2\mu_B = Z(E_f) \mu_B^2 B \quad \text{--- (2)}$$

The Pauli spin susceptibility of the electron is

$$\chi_p = \mu_0 \mu_B^2 Z(E_f) \quad \chi_p = \frac{M}{H} \quad \text{--- (3)}$$

From eqn, we know that χ_p is independent of temp.

From FD distribution we obtain

$$Z(E_f) = \frac{3N}{2E_f}$$

$N \rightarrow$ no. elec. per unit volume

$$\therefore (3) \Rightarrow \chi_p = \frac{3\mu_0 N \mu_B^2}{2E_f} = \frac{3\mu_0 N \mu_B^2}{2kT_f}$$

Where $E_f = kT_f$

$$\chi_p = \frac{3}{2} \chi \frac{T}{T_f}$$

Where $\chi = \frac{\mu_0 N \mu_B^2}{kT}$ Classical susceptibility

Since T_f is normally very high, χ_p is smaller than χ by about two orders of magnitude, which is in agreement with experimental results.

Exchange Interaction:

The Weiss theory of ferromagnetism explains about the molecular field but it is not possible to explain large value of internal field.

To explain the large internal field, Heisenberg gave an explanation which is based on the non magnetic interaction called exchange interaction between electron.

This force appears in the form of spin-spin interaction and strength of the interaction depends upon the interatomic separation. If the interatomic distance is decreased, the electron spins are decreased and the exchange force decreases and become anti parallel spins.

According to Heisenberg theory, the change interaction between electrons in different quantum states lead to a lower energy provided the spin quantum number of the both states are parallel.

∴ The exchange interaction between the electrons is given by

$$E_{ex} = -2 J_{ij} S_i S_j$$

Where J_{ij} → The exchange integral for the two atoms.

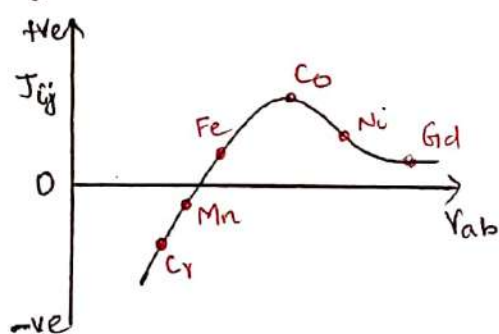
S_i → Spin angular moments associated with i^{th} state.

S_j → Spin angular moments associated with j^{th} state.

A plot of exchange Integral value (J_{ij}) and the interatomic distance (r_{ab})

r_{ab} → interatomic distance.

r_0 → the orbital radius of electron



From graph,

1. The value of J_{ij} is +ve when $\frac{r_{ab}}{r_0} > 3$ (ie) the exchange energy is +ve and hence the parallel orientation is high. Due to this atom possess ferromagnetic properties [Ex: Fe, Co, Ni, Gd]
2. The value of J_{ij} is -ve when $\frac{r_{ab}}{r_0} < 3$ (ie) the exchange energy is -ve and hence the atoms coming under this criteria possess anti-ferromagnetic properties [Ex: Cr, Mn]

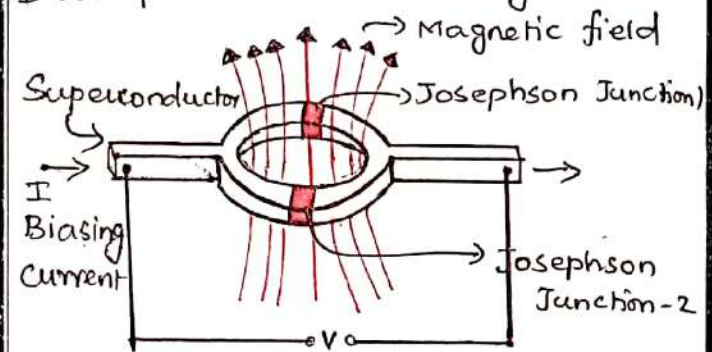
SQUID

SQUID stands for Superconducting Quantum Interference Device. It is an ultrasensitive instrument used to measure very weak magnetic field of the order of 10^{-14} tesla.

Principle:

We know that a small change in magnetic field produces variation in the quantum flux.

Description and Working



A SQUID consists of a superconducting ring which can have magnetic fields of quantum values (1, 2, 3, ...) of flux placed in between two Josephson junctions as shown in figure.

When the magnetic field is applied perpendicular to the plane of the ring, the current is induced at the two Josephson junctions. The induced current produces the interference pattern and it flows around the ring.

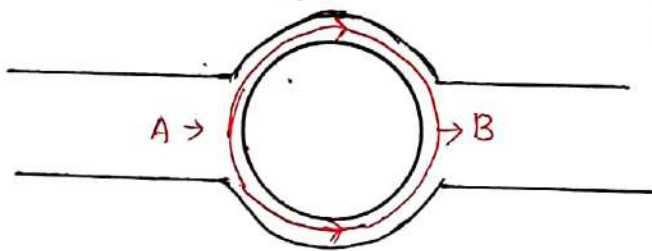
So that the magnetic flux in the ring can have the quantum value of magnetic field applied.

Application:

- (i) SQUID can be used to detect the variation of very minute magnetic signals in terms of quantum flux.
- (ii) It can also be used as storage device for magnetic flux.
- (iii) SQUID is useful in the study of earthquakes, removing para-magnetic impurities, detection of magnetic signals from the brain, heart etc.

Quantum Interference Transistor:

Electrons are made to propagate through two arms of the quantum wire ring as shown in the figure.



Suppose an electron wave enters the ring from left to right. The wave entering through 'A' gets split up into two partial

waves. A constructive interference can be expected to occur at "B" similar to the optical analogue as they travel through the same distance.

The constructive interference at the output of the device reduces the resistance of the ring. Various methods of introducing a phase difference of π between the two waves have been suggested. This leads to destructive interference which in turn will increase the resistance by reducing the current.

An external voltage can control the nature of interference and the current. This device is expected to act as a high speed transistor.

GMR Devices - Magnetic Hard Disk

Drive with GMR sensor:

GMR sensors, which has a very high magnetic sensitivity are used to read the data at greater speed.

Principle:

In Hard Disk drives, the binary data in terms of zero's (0) and one's (1) are stored by inducing.

magnetic moment in a thin mag-layer and GMR effect is used as the principle to read the data in HDD.

Here zero(0) represents missing transition and one(1) represents transition in the medium.

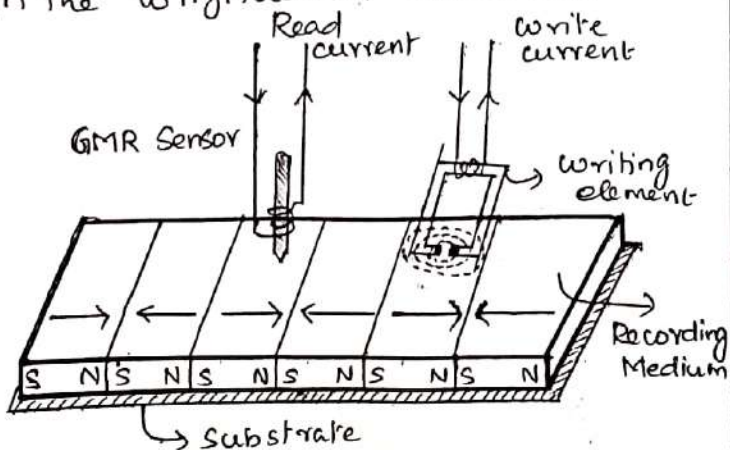
Construction:-

* The HDD consists of recording medium made up of thin layer of magnetic garnets grown over the substrate the GMR sensor.

* The substrate is made up of ferrites and anti ferromagnetic materials. This is used as reading element

* The writing element is made up of inductive magnetic transducer.

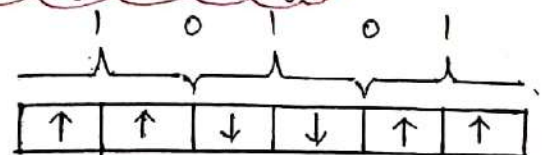
* The writing element and the GMR sensor shall be made to slide over the recording media in the longitudinal direction.



Working:- (Writing)

1. Initially the current is passed through the writing element and a magnetic field is induced in between the gap of the inductive magnetic transducer.
2. During writing, the amplitude of current is kept constant, and the direction of current is reversed.
3. Due to reversal of current the reversal of current, the magnetization orientation is reversed in the recording medium (0) from south → North.
4. When the induced magnetic field is greater than the Coercivity of the recording media, then data is recorded in the form of 1.
5. Thus one(1) is stored as data in the recording medium as a magnetic transition.
6. When there is no magnetic transition, then it is referred as zero.
7. In this way 0's & 1's are stored in the recording medium.

Reading / Retrieving.



1. GMR effect is the principle used to read/retrieve the data

2. When GMR sensor is moving near the recorded medium, then the resistance of GMR sensor varies with respect to orientation of the magnetic moments. as follows:

* When the layers are magnetised in parallel manner then the resistance is minimum, therefore maximum current flows. This represents the data as One (1)

* When the layers are magnetised in antiparallel manner, then the resistance is maximum, therefore minimum (no current) current flows. This represents the data as zero (0)

3. Therefore, with the help of the reading current, the zero's (0's) and one's (1's) can be retrieved from the magnetic hard disc.

Advantages:

- * Very large storage capacity.
- * Compact in size.
- * Non diffusive & very sensitive in reading.

Disadvantages:

- * HDD is slower than SSD
- * Consume more power
- * Data may be corrupted, due to thermal radiation.

Carrier Concentration - Intrinsic Semiconductor:-

- Elemental
- Intrinsic

The no. of charge carriers per unit volume of the material is called carrier concentration also known as density of charge carriers.

Derivation:

In intrinsic semiconductor the no. of electrons in the conduction band (n) and holes in the valence band (p) is equal to each other at $T > 0K$.

$$n = p = n_i$$

The density of electrons in the conduction band (n) is given by

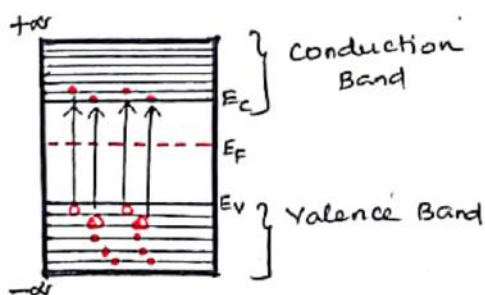
$$\int_{E_c}^{\infty} Z(E) F(E) dE \quad \text{--- (1)}$$

We know that, Density of energy states

$$Z(E)dE = \frac{4\pi}{h^3} (2m_e^*)^{3/2} E^{1/2} dE \quad \text{--- (2)}$$

Probability of Electron occupation

$$F(E) = \frac{1}{1 + e^{\frac{(E-E_f)}{k_B T}}} \quad \text{--- (3)}$$



$$\therefore n = \int_{E_c}^{\infty} \frac{4\pi}{h^3} (2m_e^*)^{3/2} E^{1/2} \frac{1}{1 + e^{\frac{(E-E_f)}{k_B T}}} dE \quad \text{--- (4)}$$

Here

m_e^* - Effective mass of Electron.
 E - KE of conduction electron

$$E = E - E_c$$

E_c - Lower conduction Energy level.

Eqn (4) can be written

$$n = \frac{4\pi}{h^3} (2m_e^*)^{3/2} \int_{E_c}^{\infty} \frac{(E-E_c)^{1/2}}{1 + e^{\frac{(E-E_f)}{k_B T}}} dE \quad \text{--- (5)}$$

We know that at $T > 0K$

$$E - E_f \gg k_B T$$

$$\frac{E - E_f}{k_B T} \gg 1 \quad \text{--- (6)} \quad e^{\frac{(E-E_f)}{k_B T}} \gg 1$$

$$\therefore 1 + e^{\frac{(E-E_f)}{k_B T}} \approx e^{\frac{(E-E_f)}{k_B T}}$$

Hence eqn (5) can be written as

$$n = \frac{4\pi}{h^3} (2m_e^*)^{3/2} \int_{E_c}^{\infty} \frac{(E-E_c)^{1/2}}{e^{\frac{(E-E_f)}{k_B T}}} dE$$

$$n = \frac{4\pi}{h^3} (2m_e^*)^{3/2} \int_{E_c}^{\infty} (E-E_c)^{1/2} e^{\frac{E_f-E}{k_B T}} dE$$

$$n = \frac{4\pi}{h^3} (2m_e^*)^{3/2} e^{\frac{E_f}{k_B T}} \int_{E_c}^{\infty} (E-E_c)^{1/2} e^{-E/k_B T} dE \quad \text{--- (6)}$$

To calculate eqn (6)

Let	when	$E = \infty$
$E - E_c = x$	$E = E_c$	$\infty - E_c = x$
$E = x + E_c$	$E_c - E_c = x$	$x = 0$
$dE = dx$	$x = 0$	$x = \infty$

∴ Eqn (6) can be written as

$$n = \frac{4\pi}{h^3} (2m_e^*)^{3/2} e^{E_f/k_B T} \int_0^\infty x^{1/2} e^{-\frac{(E_c+x)}{k_B T}} dx$$

$$n = \frac{4\pi}{h^3} (2m_e^*)^{3/2} e^{(E_f-E_c)/k_B T} \int_0^\infty x^{1/2} e^{-x/k_B T} dx$$

Using gamma function

$$\int_0^\infty x^{1/2} e^{-x/k_B T} dx = \frac{\sqrt{\pi}}{2} (k_B T)^{3/2}$$

Hence

$$n = \frac{4\pi}{h^3} (2m_e^*)^{3/2} e^{(E_f-E_c)/k_B T} \frac{\sqrt{\pi}}{2} (k_B T)^{3/2}$$

$$n = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} e^{\frac{(E_f-E_c)}{k_B T}} \quad \text{--- (8)}$$

Eqn (8) is the expression for the density of electrons in a conduction band.

Density of Holes (P)

It is given by

$$\int_{E_1}^{E_2} dp = P = \int_{E_1}^{E_2} ZCE dE [1 - F(E)] \quad \text{--- (9)}$$

Here

$$ZCE dE = \frac{4\pi}{h^3} (2m_h^*)^{3/2} e^{1/2} dE$$

here

$$m = m_h^*$$

$$E = E_v - E$$

$$1 - FCE) = 1 - \frac{1}{1 + e^{(E_v - E_f)/k_B T}}$$

By substituting and simplifying

the density of holes

$$P = 2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right] e^{\frac{(E_v - E_f)}{k_B T}} \quad \text{--- (10)}$$

Expression for intrinsic carrier concentration.

As we know in intrinsic semiconductor at any temperature above $T > 0K$

$$n = p = n_i \quad \text{--- (11)}$$

$$n \times p = n_i \times n_i = n_i^2$$

Hence

$$n_i^2 = n \times p \quad \text{given by} \quad \text{--- (12)}$$

$$n_i^2 = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} e^{\frac{(E_f - E_c)}{k_B T}} \times 2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2} e^{\frac{(E_v - E_f)}{k_B T}}$$

$$n_i^2 = 4 \left[\frac{2\pi k_B T}{h^2} \right]^3 (m_e^* m_h^*)^{3/2} e^{\frac{(E_v - E_c)}{k_B T}}$$

$$n_i = 2 \left[\frac{\sqrt{2\pi k_B T}}{h} \right]^{3/2} (m_e^* m_h^*)^{3/4} e^{-E_g/2k_B T} \quad \text{--- (13)}$$

Eqn (13) is the expression for the carrier concentration of intrinsic semiconductor.

Density of Holes :-

It is given by

$$\int_{E_1}^{E_2} dp = P = \int_{E_1}^{E_2} ZCE dE \cdot [1 - FCE]$$

Hence

$$Z(E) dE = \frac{4\pi}{h^3} (2m_h^*)^{3/2} E^{1/2} dE$$

Hence $m = m_h^*$

$E = E_V - E$

$$1 - F(E) = 1 - \frac{1}{e^{(E-E_F)/k_B T}}$$

Eqn ①

$$P = \int_{-\infty}^{E_V} \frac{4\pi}{h^3} (2m_h^*)^{3/2} (E_V - E)^{1/2} e^{(E-E_F)/k_B T} dE$$

$$P = \frac{4\pi}{h^3} (2m_h^*)^{3/2} e^{-E_F/k_B T} \int_{-\infty}^{E_V} (E_V - E)^{1/2} e^{E/k_B T} dE$$

— (2)

Let

$E_V - E = x$	When $E = -\infty$	When $E = E_V$
$E = E_V - x$	$E_V - (-\infty) = x$	$E_V - E_V = x$
$-dE = -dx$	$E_V + \infty = x$	$x = 0$
	$x = \infty$	

Eqn ② becomes

$$P = \frac{4\pi}{h^3} (2m_h^*)^{3/2} e^{-E_F/k_B T} \int_0^{\infty} x^{1/2} e^{-x/k_B T} dx$$

$$P = \frac{4\pi}{h^3} (2m_h^*)^{3/2} e^{-E_F/k_B T} \int_0^{\infty} x^{1/2} e^{-x/k_B T} dx$$

Using Gamma function

$$\int_0^{\infty} x^{1/2} e^{-x/k_B T} dx = \frac{\sqrt{\pi}}{2} [k_B T]^{3/2}$$

Hence

$$P = \frac{4\pi}{h^3} (2m_h^*)^{3/2} e^{-E_F/k_B T} \frac{\pi^{1/2}}{2} (k_B T)^{3/2}$$

$$P = 2 \cdot \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2} e^{-\frac{(E_V - E_F)}{k_B T}}$$

The above equation is the expression for the density of holes in the valence band.

Extrinsic Semiconductor

Def:

Impure Semiconductors are the one in which charge carriers generated by adding impure atoms to the pure semiconductors.

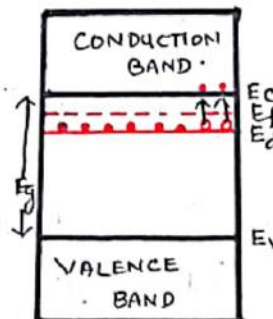
Types:

These are classified into two types based on the type of impurity

- (i) n type (penta valent impurity)
- (ii) p type (Trivalent impurity)

Carrier Concentration - n type Semiconductor

* The energy level diagram is shown in the figure.



* The energy level of excess electron is called donor energy level (E_D). This is located above valence band.

At equilibrium
Density of Electron in the conduction Band (n) = Density of holes in the Donor energy level (n_h)

$$n = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} e^{\frac{E_f - E_c}{k_B T}} \quad \text{--- (1)}$$

m_e^* → Effective mass
 k_B → Boltzmann Constant

$$\text{No. of holes (or) donors} = N_d [1 - F(E_d)] \quad \text{--- (2)}$$

$F(E_d)$ → Probability of Electron in donor energy level.

$1 - F(E_d)$ → Probability of ionized donors

N_d → Total no. of donor atoms per unit volume.

$$\therefore F(E_d) = \frac{1}{1 + e^{\frac{E_d - E_f}{k_B T}}}$$

$$\begin{aligned} \therefore \text{Eqn. (2)} &= N_d \left[1 - \frac{1}{1 + e^{\frac{E_d - E_f}{k_B T}}} \right] \\ &= N_d \left[\frac{1 + e^{\frac{E_d - E_f}{k_B T}} - 1}{1 + e^{\frac{E_d - E_f}{k_B T}}} \right] \\ &= N_d \frac{e^{\frac{E_d - E_f}{k_B T}}}{1 + e^{\frac{E_d - E_f}{k_B T}}} \end{aligned}$$

$E_d < E_f$ therefore $E_d - E_f$ -ve

$$\therefore 1 + e^{\frac{E_d - E_f}{k_B T}} \approx 1$$

∴ The above eqn can be written as

$$\text{The density of ionised donors (or) holes } n_h = N_d e^{\frac{E_d - E_f}{k_B T}}$$

∴ $n = n_h$

$$2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} e^{\frac{E_f - E_c}{k_B T}} = N_d e^{\frac{E_d - E_f}{k_B T}} \quad \text{--- (3)}$$

By Rearranging the above eqn

$$\frac{e^{\frac{E_f - E_c}{k_B T}}}{e^{\frac{E_d - E_f}{k_B T}}} = \frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}}$$

$$e^{\frac{E_f - E_c - E_d + E_f}{k_B T}} = \frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}}$$

$$e^{\frac{2E_f - (E_c + E_d)}{k_B T}} = \frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}}$$

Taking log on both sides

$$\frac{2E_f - (E_c + E_d)}{k_B T} = \log \left[\frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right]$$

$$2E_f - (E_c + E_d) = k_B T \log \left[\frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right]$$

$$2E_f = E_c + E_d + k_B T \log \left[\frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right]$$

$$E_f = \frac{E_c + E_d}{2} + \frac{k_B T}{2} \log \left[\frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right] \quad \text{--- (4)}$$

Carrier Concentration:-

By substituting eqn (A) in eqn (1)

we have

$$n = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} \exp \left[\frac{E_d + E_c}{2k_B T} + \frac{k_B T}{2} \log \frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right] - E_c$$

$$n = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} \exp \left[\frac{E_d + E_c}{2k_B T} + \frac{E_c}{k_B T} + \frac{1}{2} \log \frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right]$$

$$n = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} \exp \left[\frac{E_d + E_c - 2E_c}{2k_B T} + \frac{1}{2} \log \frac{N_d}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right] \quad \text{--- (5)}$$

$$n = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} e^{\frac{E_d - E_c}{2k_B T}} \cdot e^{\log \left[\frac{N_d^{1/2}}{2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2}} \right]^{1/2}}$$

$$n = 2 \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/2} e^{\frac{E_d - E_c}{2k_B T}} \frac{N_d^{1/2}}{2^{1/2} \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/4}}$$

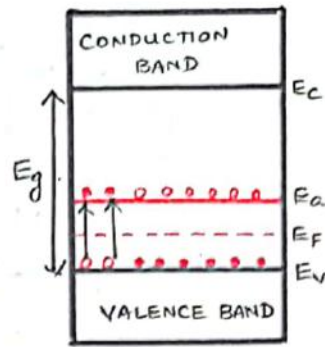
$$n = \left[2 N_d \right]^{1/2} \left[\frac{2\pi m_e^* k_B T}{h^2} \right]^{3/4} e^{\frac{E_d - E_c}{2k_B T}} \quad \text{--- (6)}$$

Eqn (6) is the expression for Carrier concentration of n-type Semiconductor, in terms

P-Type Semiconductor:

* The Energy level diagram is shown in the figure

* Here the excess no. of holes from a new energy level (E_a) acceptor level just below the Conduction Band.



We know that the density of holes in the valence band.

$$p = 2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2} e^{(E_v - E_f)/k_B T} \quad \text{--- (1)}$$

E_v → Top energy level of valence Band
 E_a → Acceptor Energy level
 E_f → Fermi Energy level.

Density of Electrons in the acceptor energy level is given by

$$n_a = N_a [F(E_a)]$$

$$n_e = N_a \frac{1}{1 + e^{\frac{E_a - E_f}{k_B T}}} \quad \text{--- (2)}$$

Since $E_a - E_f \gg k_B T$ (or) $\frac{E_a - E_f}{k_B T} \gg 1$

$$\therefore 1 + e^{(E_a - E_f)/k_B T} \approx e^{(E_a - E_f)/k_B T}$$

$$\therefore n_e = N_a e^{\frac{(E_f - E_a)}{k_B T}} \quad \text{--- (3)}$$

At equilibrium,

No. electrons in the acceptor energy level (p) = No of holes in valence band (n_e)

$$2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2} e^{\frac{(E_v - E_f)}{k_B T}} = N_a e^{\frac{(E_f - E_a)}{k_B T}} \quad \text{--- (4)}$$

$$\frac{e^{\frac{(E_v - E_f)}{k_B T}}}{e^{\frac{(E_f - E_a)}{k_B T}}} = \frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}}$$

$$e^{\frac{(E_v - E_f - E_f + E_a)}{k_B T}} = \frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}}$$

$$e^{\frac{(-2E_f + E_v + E_a)}{k_B T}} = \frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}}$$

Taking log on both sides,

$$\frac{-2E_f + E_v + E_a}{k_B T} = \log \frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}}$$

Rearranging Equation,

$$E_f = \frac{E_a + E_v}{2} - \frac{k_B T}{2} \log \left[\frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}} \right] \quad \text{---(b)}$$

The density of holes in the p type can be written by substituting equation (b) in eqn (1)

$$p = 2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2} e^{\frac{(E_v - E_f)}{k_B T}}$$

Here $\frac{(E_v - E_f)}{k_B T}$ can be rearranged as follows,

$$= \exp \left[\frac{E_v - \left[\frac{E_a + E_v}{2} \right] - \frac{k_B T}{2} \log \left[\frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}} \right]}{k_B T} \right]$$

$$= \exp \left[\frac{2E_v - E_a - E_v}{2k_B T} + \frac{1}{2} \log \left[\frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}} \right] \right]$$

$$= \exp \left[\frac{E_v - E_a}{2k_B T} + \frac{1}{2} \log \left[\frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}} \right] \right]$$

∴ Eqn (1) can be written as

$$p = 2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2} \exp \left[\frac{E_v - E_a}{2k_B T} + \frac{1}{2} \log \left[\frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}} \right] \right]$$

$$p = 2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2} e^{\frac{E_v - E_a}{2k_B T}} \cdot \left[\frac{N_a}{2 \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/2}} \right]^{1/2}$$

$$p = (2N_a)^{1/2} \left[\frac{2\pi m_h^* k_B T}{h^2} \right]^{3/4} e^{\frac{(E_v - E_a)}{k_B T}} \quad \text{---(7)}$$

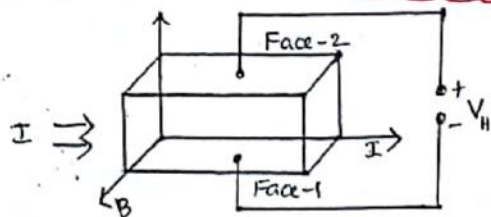
Eqn (7) is the expression for the carrier concentration of 'p' type semiconductor.

Hall Effect:

When a conductor carrying a current (I) is placed perpendicular to a magnetic field (B) a potential difference is produced inside the conductor in a direction perpendicular to current and magnetic field.

This phenomenon is known as "Hall effect" and generated voltage is called Hall "voltage"

Hall Effect in n-type Semiconductor & P-type



Consider n-type semiconductor in the form of rectangular slab. Current (I) flow in x-direction magnetic field (B) is applied in z-direction. Due to Hall effect voltage developed along y-direction (in fig). current flow due to electron flow.

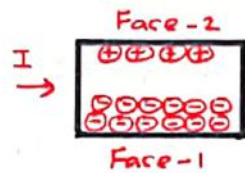
Electrons moving with velocity v' , experience downward force.

Force due to magnetic field (Downward) } = $B e v'$ — (1)

Force due to potential difference } = $e E_H$ — (2)

At equilibrium (1) = (2)

$B e v' = e E_H$
 $E_H = B v'$ — (3)



We know that

Current density

$J_x = -n e v'$
 $v' = \frac{-J_x}{n e}$ — (4)

Substitute eqn (4) in eqn (3)

$E_H = B \left(\frac{-J_x}{n e} \right)$

$E_H = R_H J_x B$ — (5)

∴ Hall coefficient

$R_H = \frac{E_H}{J_x B}$

where $R_H = \frac{-1}{n e}$
 -ve sign indicates Elec. field in -ve y axis

Similarly in P-type semiconductor Current flow due to flow of holes (+ve charge)

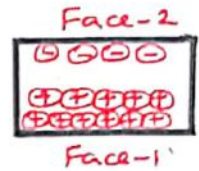
Compare with n-type semiconductor current density $J_x = p e v'$

$v' = \frac{J_x}{p e}$ — (6)

Substitute eqn (6) in (3)

$E_H = R_H J_x B$ — (7)

$R_H = \frac{1}{p e}$



Hall coefficient interms of Hall voltage

Hall voltage $V_H = E_H t$ — (8)

where $E_H \rightarrow$ Hall field.

Substitute eqn (7) in eqn (8)

$V_H = R_H J_x B t$ — (9)

Area of the sample $A = \text{thickness} \times \text{breadth}$
 $A = b t$

Current density $J_x = \frac{I_x}{A}$
 $J_x = \frac{I_x}{b t}$ — (10)

Substitute eqn (10) in eqn (9)

$V_H = \frac{R_H I_x B t}{b t}$
 $V_H = \frac{R_H I_x B}{b}$ — (11)

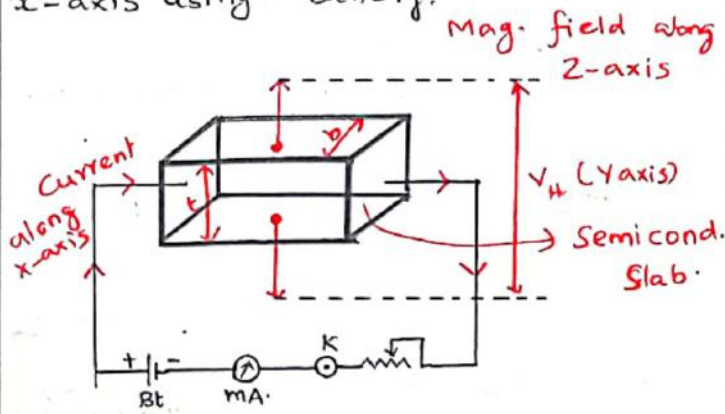
$R_H = \frac{V_H b}{I_x B}$ — (12)

Eqn (12) gives Hall coefficient in interms of hall voltage.

Experimental Determination of Hall Coefficient

A semiconductor slab of thickness 't' and breadth 'b' is

taken and current is passed through x-axis using battery.



The slab is placed between poles of an electromagnet. Magnetic field is applied along z-axis. The Hall voltage (V_H) is measured by placing two probes at the centre of the top and bottom of the slab.

By measuring Hall voltage, Hall coefficient is determined from the formula

$$R_H = \frac{V_H b}{I_x B}$$

Mobility of charge Carriers:

We know that, Hall coefficient

$$R_H = -\frac{1}{ne}$$

The above expression is valid only for conductors, where the velocity is taken as drift velocity.

For n-type Semiconductor

$$R_H = -\frac{1.18}{ne}$$

$$ne = -\frac{1.18}{R_H} \text{---(1)}$$

For p-type Semiconductor

$$R_H = \frac{1.18}{pe} \quad pe = \frac{1.18}{R_H} \text{---(2)}$$

Electrical conductivity

for n-type Semiconductor

$$\sigma_e = ne\mu_e \text{---(3)}$$

$$\text{(1)} \Rightarrow \mu_e = \frac{\sigma_e}{-\frac{1.18}{R_H}}$$

$$\mu_e = \frac{-\sigma_e R_H}{1.18} \text{---(4)}$$

For p-type Semicond.

$$\sigma_h = pe\mu_h \text{---(5)}$$

$$\text{(2)} \Rightarrow \mu_h = \frac{\sigma_h}{\frac{1.18}{R_H}}$$

$$\mu_h = \frac{\sigma_h R_H}{1.18}$$

---(6)

Application of Hall Effect:-

- (i) Used to determine whether the material is p-type or n-type Semiconductor.
- (ii) Used to find the carrier Concentration

$$n = \frac{1}{eR_H}$$

- (iii) Used to find the mobility of Charge carriers

$$\mu_e = \sigma_e R_H, \mu_h = \sigma_h R_H$$

Schottky Diode:-

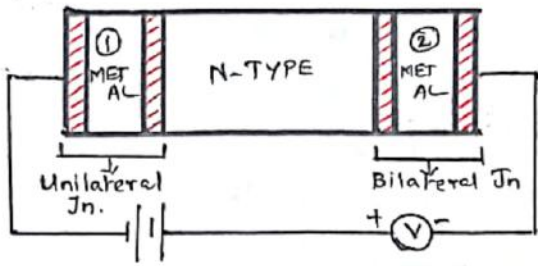
Schottky diode is a unilateral device, in which current flow from metal to semiconductor in one direction.



Construction:-

A Schottky diode also called as Schottky barrier diode. It is made up of 2 junctions.

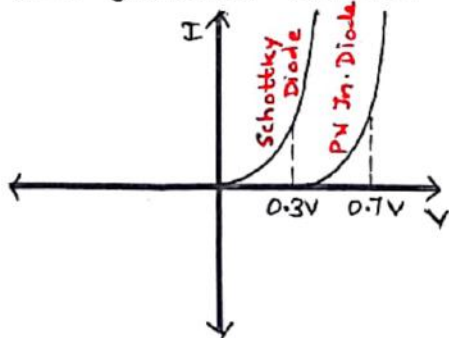
- (i) Unilateral [Metal-Semiconductor]
- (ii) Bilateral [Metal-Semiconductor]



The Schottky diode act as a terminal device in which metal 1 and Semiconductor formed at one end act as anode with unilateral junction, metal 2 and Semiconductor formed at other end act as cathode with bilateral junction.

Working:

Applying forward bias, the voltage applied to diode and their corresponding current is measured. The V-I curve is drawn for Schottky diode as compared with P-N Junction diode.



As per V-I curve, during forward bias for a Schottky diode I increase enormously even for

small applied V, due to 3 component of current occurs in schottky diode

Application:

- * Due to low voltage drop, they are used in high switching system
- * They are used in BJT
- * It is used in Radio frequency application.
- * It is used in high power supply

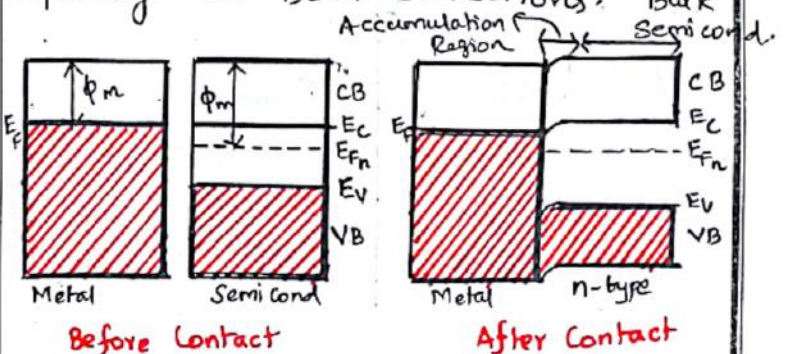
Ohmic Contacts:

Definition:

An ohmic contact is a type of metal semiconductor junction. It is formed by a contact of a metal with a heavily doped semiconductor.

When the semiconductor has a higher work function than that of metal, then the junction formed is called the ohmic junction.

Here the current is conducted equally in both directions.



Working:

Fermi levels of the metal and Semiconductor are at different positions before contact. [Fig (i)]

After contact, at equilibrium the electrons move from the metal to the empty states in the conduction band of Semiconductor.

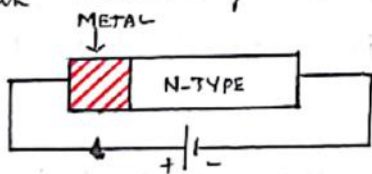
∴ An accumulation region near the interface is appeared. (Semiconductor side)

Fermi levels after contact are shown in [fig (ii)].

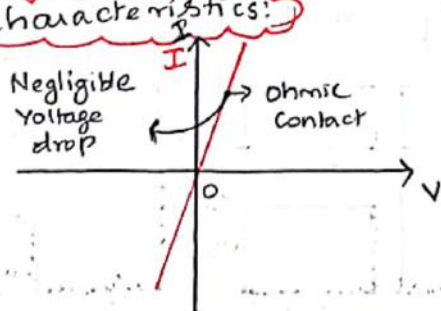
Accumulation region has a higher conductivity than the bulk Semiconductor due to higher concentration.

Ohmic contact behaves as a resistor conducting in both forward and reverse bias. (Fig. iii).

The resistivity is determined by the bulk resistivity of the Semiconductor.



V-I characteristics:



The current density is proportional to the potential across the junction.

Ohmic contacts are non-rectifying and show negligible voltage drop and resistance irrespective of the direction and magnitude of current.

Applications:

The use of ohmic contact is to connect one semiconductor device to another, an IC or to connect an IC to its external terminals

OPTOELECTRONICS DEVICE - LIGHTDETECTORS:

* Opto electronic devices such as **light detectors** (or) **photo detectors** are the devices which convert the **light signal** into **electrical signals**.

* The **Three** main photo detectors used in **optical fiber communication** system are

- (i) P-i-n - Photo diode (PIN Diode)
- (ii) Avalanche Photo diode (APD)
- (iii) PN junction photo detector

→ **P-i-n - Photo Diode (PIN Diode)**

* Principle:

• This Diode works in **Reverse bias**. Under reverse bias, light is made to fall on **neutral region**.

• Electron hole pairs are generated and accelerated by the external electric field, which results in **photo-current**.

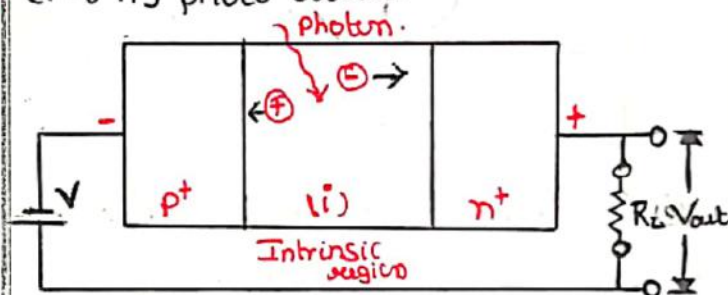
* Construction:

• It consists of three regions **P, i and n**.

• The p-n regions are made up of semiconductor material [**silicon, germanium**].

• The intrinsic region is a neutral, where it is at the centre of the p-type and n-type regions and it is lightly doped with n-material.

• Since the p-n region is separated by an **intrinsic region (i)**, it is called as **positive - intrinsic - negative (P-i-n) photo diode**.



Working:

* The PIN Diode is given very **high reverse bias** to attract the charge carriers from the **intrinsic region**.

* The photon incident on the intrinsic region produces **electron-hole** pair, by the transfer of electrons from **valence band** to **conduction band**, leaving a hole.

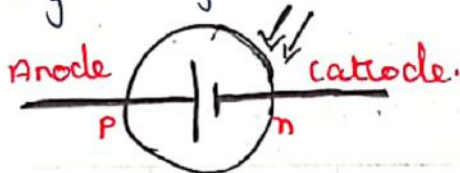
* The movement of electrons in the conduction band creates flow of charges. Hence **light energy** is converted into **electrical energy**.

Solar Cell:

* Principle:

A solar cell is basically a P-N junction photo diode, which converts solar energy (light energy) into electrical energy. With larger efficiency of photon absorption.

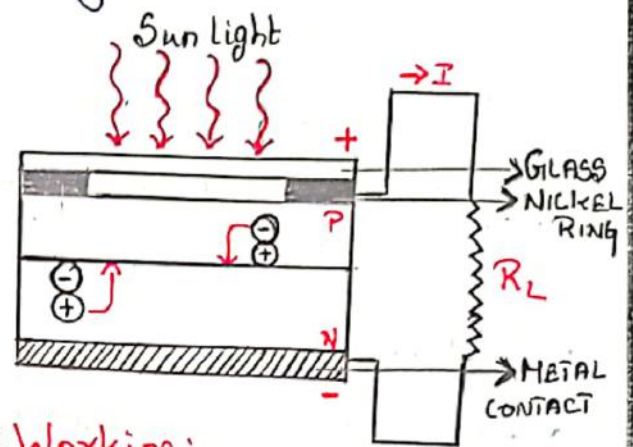
* The symbol of the solar cell



* Construction:

- ⊙ A solar cell is made up of a heavily doped 'p' and 'n' type material.
- ⊙ The P-N diode is packed in a can with glass window on top such that light may fall upon P and N type material.
- ⊙ The thickness of the p-region and n-region is very small. Therefore charge carriers generated in this region can easily diffuse to the junction.
- ⊙ Nickel ring at the top and metal at bottom act as terminals.

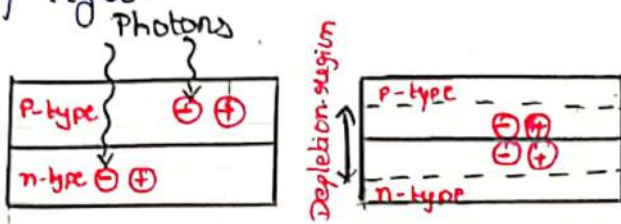
⊙ The two terminals connected to the load resistance R_L through the ohmic contacts.



* Working:

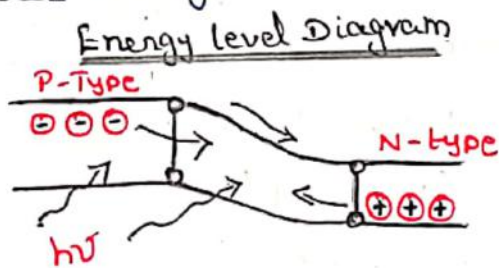
- Light radiation is allowed to fall on P-N junction diode, without load resistance (R_L).
- The photon energy is sufficient to break the covalent bond and produce electron-hole pairs.
- These electrons and holes quickly diffuses and reaches the depletion region.
- Therefore the strong barrier electric field existing in the junction.
- The minority carrier electrons in the p-side cross the barrier potential to reach n-side and the holes in n-side move to the p-side.

- The minority current is directly proportional to the illumination of light.



- The electrons and holes accumulate on either side of the junction, which gives rise to open-circuit voltage (V_0).

- Load Resistance R_L is connected across the diode, reverse current I_R flows through the circuit.



* Merits:

- Utilize renewable energy.
- Eco-friendly
- Pollution free
- Life time durability high.

* Demerits:

- Cost is very high.
- Seasonal energy
- Occupies more energy.

* Uses:

- Power production.
- Used in artificial satellite and space probes.

LIGHT EMITTING DIODE (LED)

* Definition:

- LED is a semiconductor P-n junction diode which converts electrical energy to light energy under forward biasing.

Symbol:

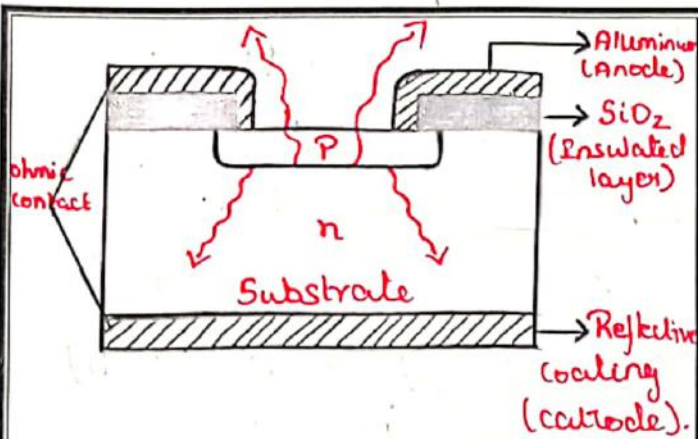


* Principle:

- Injection luminescence is the principle used in LEDs.
- The injection of electrons into the p-region from n-region makes a direct transition from conduction band to valence band. The electrons recombine with holes and emit photons of energy E_g .

* Construction:

- The p-n junction is formed by diffusion techniques by doping silicon with GaAs crystal.
- Where, n-type is grown on a substrate and a p-type layer is deposited on it by diffusion.



⊙ To increase the radiative recombination, the thickness of n -layer is higher than the thickness of 'P' layer.

⊙ Ohmic contacts are made by aluminium in such a way that top layer "p" material is left uncovered for the emission of light, where the carrier recombination takes place.

* Working:-

⊙ Under forward biasing, Majority charge carriers of n -type (electrons) moves to p -type as minority carriers.

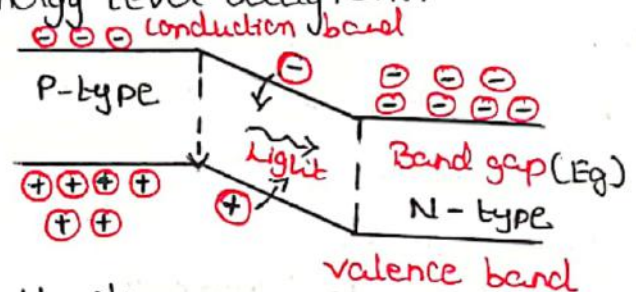
⊙ Similarly, majority charge carriers of p -type (holes) moves to n -type as minority carriers.

⊙ By this process, excess of minority carriers are injected in both p and n regions, This is called minority carrier injection.

⊙ Biasing voltage is further increased, excess minority carriers diffuse away from the junction and directly recombine with the majority carriers.

⊙ Therefore electron-hole recombination process occurs, thereby photon is emitted.

Energy level diagram:



* Merits:

- Very fast Response.
- Cost is very low.
- Smaller in size.
- Long life time.

* Demerits:

- Power output is low.
- Less Directional.
- Intensity is lesser than laser.

* Applications:

- Used in display devices.
- Used in pilot light.
- Used in indicator lamp.
- IR LEDs used in wire-less communication.

LASER DIODE:

* Definition:

It is a specially fabricated P-n junction diode. This diode emits laser light when it is forward-biased.

* Principle:

Recombination of electron-hole pairs leads to **emission** of light in forward biasing known as **recombination radiation**.

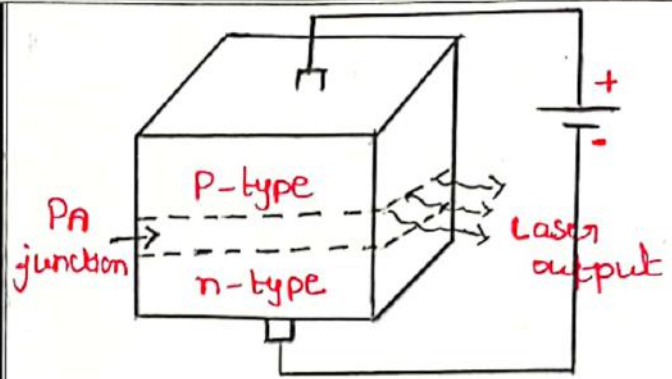
* Construction:

① The active medium is a P-n junction diode made from a single crystal of **GaAs**.

② The crystal is cut in the form of platelet (0.5mm-thickness) consists of two regions n-type & p-type.

③ Metal electrodes are connected to both upper & lower surfaces of the S.C diode.

④ Forward bias voltage is applied through metal electrodes.



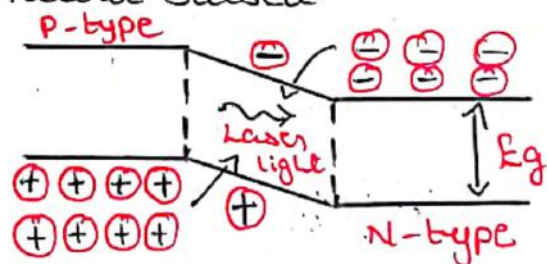
⑤ The photon emission is stimulated in a very thin layer of pn junction.

⑥ The end faces of the Pn junction are **well polished** and parallel to each other.

⑦ It acts as an optical **resonator** through which the emitted light comes out.

* Working:

① When the pn-junction is forward biased.



② Electrons & holes are **injected** into junction region.

③ The region around junction contains a large number of electrons in the **conduction band** and holes in **valence band**.

① During recombination, light photons are produced.

② During Forward bias Voltage is increased, more photons are emitted.

③ These photons trigger a chain of stimulated recombination^{-ons} more photons in phase travel forth & back by two polished surfaces of junction.

④ After gaining enough strength Laser beam of wavelength 8400 \AA is emitted from the junction. $E_g = hc/\lambda$.

* Merits:

- ① Compact in size.
- ② High efficiency.
- ③ Less power consumption.
- ④ Waveform is continuous/pulsed.

* Demerits:

- ① Output has large divergence
- ② poor coherence & Monochromaticity

* Applications of Laser diodes:

- ① Used in optical communication.
- ② Used in Barcode reader.
- ③ Used in printing industry.
- ④ Used as writing head in Disc drives.
- ⑤ Used in various industry applications such as cladding welding etc.

OLED - Organic LED:

* Definition:

- ① OLED are solid state devices made up of thin films of organic molecules that produce light with the application of electricity.
- ② It is also known as light emitting polymers (LEP) or Organic electro luminescence.
- ③ Thickness of these layers is around 100 - 500 nm thick.

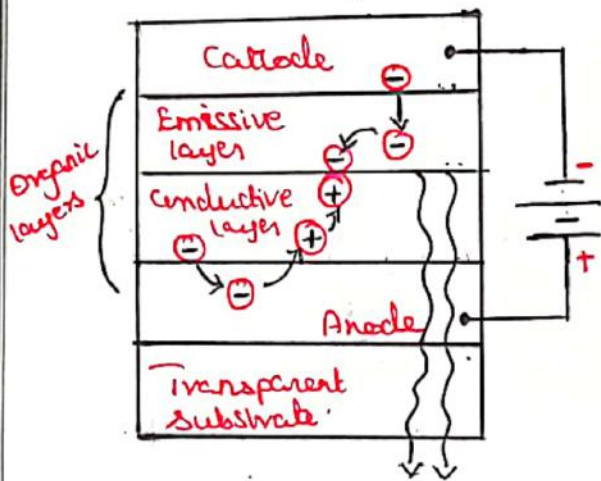
* Principle:

An electron moves from the cathode to the emissive layer

and hole moves from the anode to the conductive layer and they recombine to produce photons.

* Construction:

⊙ It is constructed with different layers of polymers coated with Organic compound.



⊙ It consists of an emissive layer made up of **poly-fluorine** and a conductive layer made up of **poly-aniline** kept between cathode and anode substrate.

⊙ This whole layers placed over transparent electrode layers.

* Working:

⊙ Forward bias voltage is applied across the OLED

⊙ Due to this cathode diffuse electron into emissive layer.

⊙ Anode gets an electron from conductive layer & produces a hole in conductive layer.

⊙ Thus, emissive layer becomes rich in **negative charged** particles & conductive layer becomes rich in **positive charged** particles.

⊙ Due to the electrostatic force, electrons and holes, come closer & recombine with each other.

⊙ In organic sc, holes move faster than electrons.

⊙ This recombination produces light and it is emitted through the transparent substrate.

* Merits:

- ① It is thin & flexible.
- ② Light weight-
- ③ Larger field view
- ④ Emission is brighter than normal light (LED'S).

* Demerits:

- ① Manufacturing cost is high.
- ② Easily damaged.
- ③ Maintenance is high.

* Application:

- ① Used in cell phones, car radios, digital cameras.
- ② Used in TV screens, computers displays, advertising
- ③ Automotive dash boards
- ④ Used in flexible display boards.

ELECTRO-OPTIC MODULATORS

* Electro-Optic Effect:

The phenomenon in which the optical properties of a material change in response to a varying electrical field is known as electro-optic effect and the crystals with special optical properties that allow an electrical signal to control and modulate a beam of light are known as Electro-optic modulators.

Types of electro-optic modulators

Based on type of the modulated beam, electro-optic modulators are classified as

- * Intensity modulator.
- * phase modulator
- * Amplitude modulator.
- * Polarization modulator.

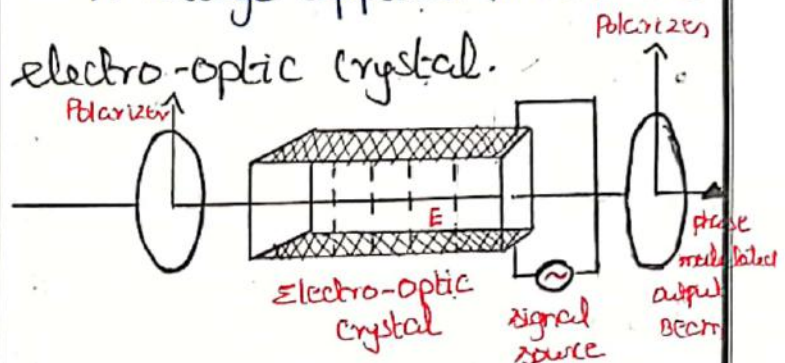
* Principle:

Electro-optic modulators consists of a non-linear crystal [lithium niobate]. The refractive

index varies with strength of the applied electric field. Based on the linear electro-optic effect.

* Operation:

* A voltage applied across the electro-optic crystal.



* Due to plane-polarized light propagating through the crystal to resolved into two components.

* The change in retardation between two components is proportional to the magnitude of the electric field.

* A crossed polarizer analyzes the output beam, resulting in intensity modulation.

* Significance:

• Modify the properties of a travelling light wave.

* Application:

- Communications.
- Information processing.
- Digital signal processing.

* Properties of electro-optic material:

- Large change in refractive index per volt.
- High optical quality and transmission.
- Low dielectric constant.

PLASMONICS:

* Plasmon:

Plasmon is a collective wave where billions of electrons oscillate in synchronization.

* Plasmonics:

Plasmonics refers to the resonant interaction between electromagnetic radiation and free electrons at the interface between a metal and a dielectric material.

* Principle:

Surface Plasmon Resonance

High intense photons and free electron interaction causes

generation of density electron waves called surface plasmons.

* Conduction electrons on the nanoparticle surface of the plasmonic material undergo a collective oscillation when excited by light at specific wavelengths.

* This oscillation, which is known as surface plasmon resonance (SPR).

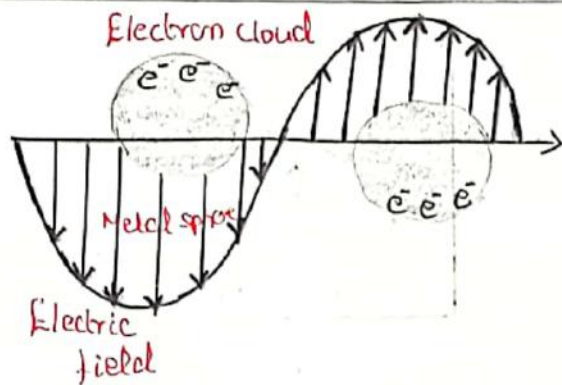
* Theory:

* The plasmon resonance of the free electrons in the metal nanoparticle, studied by polarization - bility.

* When an excitation occurs, the electrons will oscillate by external electric field.

* On metal's surface, electrons will make each other to oscillate. After excitation waves will appear [longitudinal & damping]

* Surface plasmons polaritons resonance, controlled by size.



and optical properties of nano-particle composition and medium in which the particles are embedded.

* Application:

- * Superfast optical computers
- * Tumor killing cancer therapies
- * Laser for self-driving cars.

Switching Devices

The opto-electronic switching devices are very useful for computing and light activated logic gates applications.

* Definition:

Switching refers to a phenomenon in which transmission of an optical field through a device is switched among two or more possible states by optical

means.

* Types of Optical Switching:

There are two types of optical switching.

* P-i-n [Multi Quantum Well]

- self electro optic effect (SEEO) device.

* The Quantum Controlled Stark Effect [QCSE]

* Self Electro Optic Effect [SEEO]

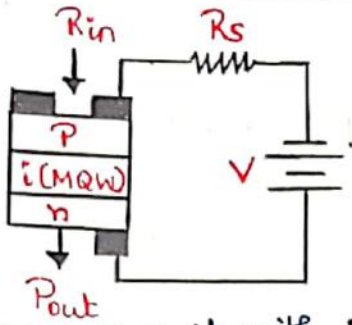
* Principle:

The photocurrent flowing through the current including series resistor, changes the voltage across the modulator, this influences its absorption and transmission.

* Circuit:

* In p-i (MQW)-n diode, by the reverse bias voltage, the tunneling current varies.

* The photocurrent-bias voltage exhibits Negative differential resistance (NDR).



- * SEED circuit with series resistor
- * P_{in} \rightarrow incident optical power

$P_{out} = I^2 R_s$ is electric output power.

- * I is the photo current flowing through resistance (R_s)

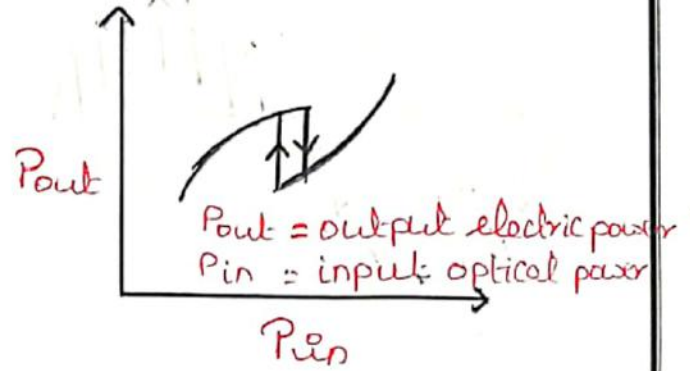
* Operation

* The photo current increases due to recombination of electrons and holes [tunneling of charge carriers]

* The negative bias across the diode decreases. The heavy hole absorption peak is shifted to higher energies.

* Voltage drops $I^2 R_s$ across the series resistor increases.

* When the photo current decreases and correspondingly output electric power decreased.



* Increase of input optical power increases the output electric power due to ordinary photon absorption by the diode.

* Photonic switching can also be illustrated with two beams, one for transmission and one for control.

DENSITY OF STATE FOR SOLIDS:-

Def:- Electron density is the number of electron per unit volume in a material. It is determined by using density of state.

In solid, the total number of electron energy states N with energy upto E is determined based on quantum mechanics using,

$$N = \left(\frac{8\pi}{3} \right) (2mE)^{3/2} \left(\frac{a^3}{h^3} \right) \quad \text{--- (1)}$$

where $a^3 \Rightarrow$ volume of material.

$E \Rightarrow$ Maximum energy level

$m \Rightarrow$ mass of electron

$h \Rightarrow$ Planck's Constant

No. of Energy state } $n = \frac{N}{a^3}$
per unit volume

$$n = \left(\frac{8\pi}{3} \right) \frac{(2mE)^{3/2}}{h^3} \quad \text{--- (2)}$$

Density of energy state nothing but the number of available electron energy state per unit volume per unit energy.

ie $Z(E) = \frac{dn}{dE}$

$$= \frac{d}{dE} \left[\frac{8\pi}{3} \frac{(2mE)^{3/2}}{h^3} \right]$$

$$= \frac{8\pi}{3} \frac{(2m)^{3/2}}{h^3} \frac{d(E)^{3/2}}{dE}$$

$$= \frac{8\pi}{3} \frac{2^{3/2} \cdot m^{3/2} \left[\frac{3}{2} E^{3/2-1} \right]}{h^3}$$

$$= \frac{8\pi}{3} \cdot \frac{2 \cdot 2^{1/2} \cdot m^{3/2}}{h^3} \times \frac{3}{2} E^{1/2}$$

$$Z(E) = \frac{8\pi\sqrt{2} m^{3/2}}{h^3} \sqrt{E} \quad \text{--- (3)}$$

At 0 K, the ~~total~~ number of free electron per unit volume (or) electron density,

from eqn. (2)

$$n_e = \frac{8\pi}{3} \left(\frac{2mE_F}{h^3} \right)^{3/2} \quad \text{--- (4)}$$

The nanoparticle give Unique electronic properties, so that the small volume material differ from bulk solid is the number of available energy state.

Significance between Fermi Energy &

Volume of the Material:-

Defn It is defined as the highest energy level occupied by the electron at 0 K in metal.

Distribution of energy in solid have wide energy band whereas atom have thin, discrete energy state.

from eqn. (6)

Fermi Energy of Conductor

$$E_f = \frac{h^2}{2m} \left(\frac{3n_e}{8\pi} \right)^{2/3}$$

Here n_e only variable, and others

are constant so,

$$i.e. E_f \propto n_e^{2/3}$$

Therefore, fermi energy of the conductor just depends on the number of free electron per unit volume, " n_e ".

DENSITY OF STATE IN QUANTUM WELL,

QUANTUM WIRE & QUANTUM DOT:-

BULK STRUCTURE:-

Density of state

$$Z(E) = \frac{8\pi\sqrt{2} m^{3/2} (E - E_c)^{1/2}}{h^3}$$

where; $E_c \Rightarrow$ Bottom of Conduction Band.

$m^* \Rightarrow$ Effective mass of Electron.

Quantum Well:-

The electron can move freely in two

direction and Confined in one direction

$$\therefore Z(E) = \frac{4\pi m^*}{h^2}$$

Quantum Wire:-

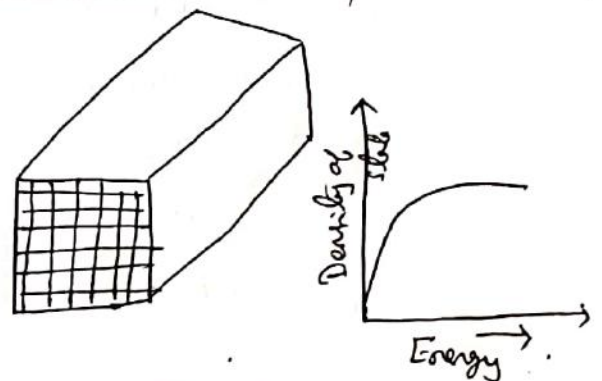
The Carrier can move freely along one direction, the remaining two direction are Confined.

$$\therefore Z(E) = \frac{2\sqrt{2} m^* (E - E_i)^{1/2}}{h}$$

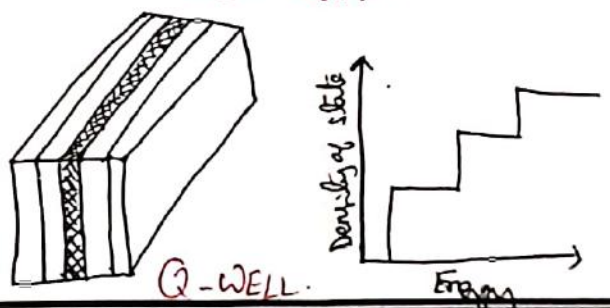
Quantum Dot:-

All direction are Confined and no direction the electron move as freely.

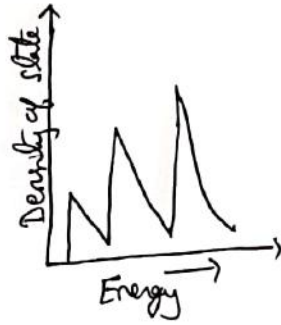
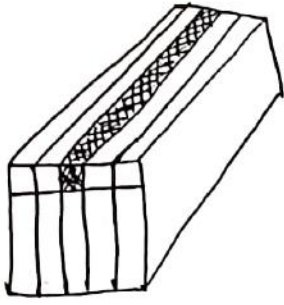
$$\therefore Z(E) = \delta(E - E_i)$$



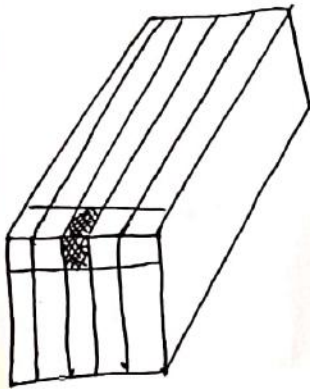
3D - BULK -



Q - WELL -



Quantum Wire.



Quantum Dot.

QUANTUM WELL LASER:-

A quantum well laser is a laser diode in which the active region are narrow with the quantum confinement occurs. Laser diode are formed in compound semiconductor material and it can emit light efficiently.

The wavelength of the light depends on the width of the active region.

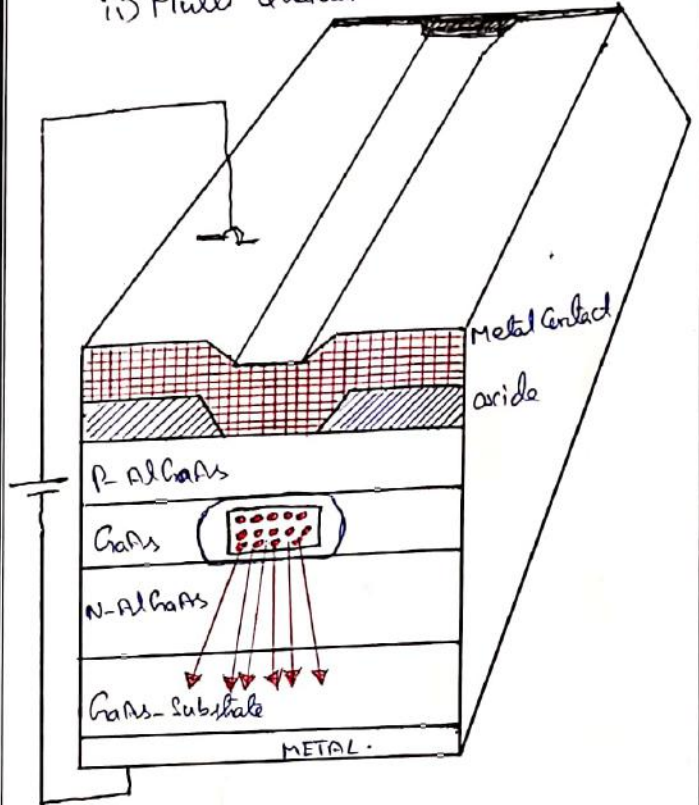
Principle:-

The combination of electron from the conduction band to the holes in valence band produce laser.

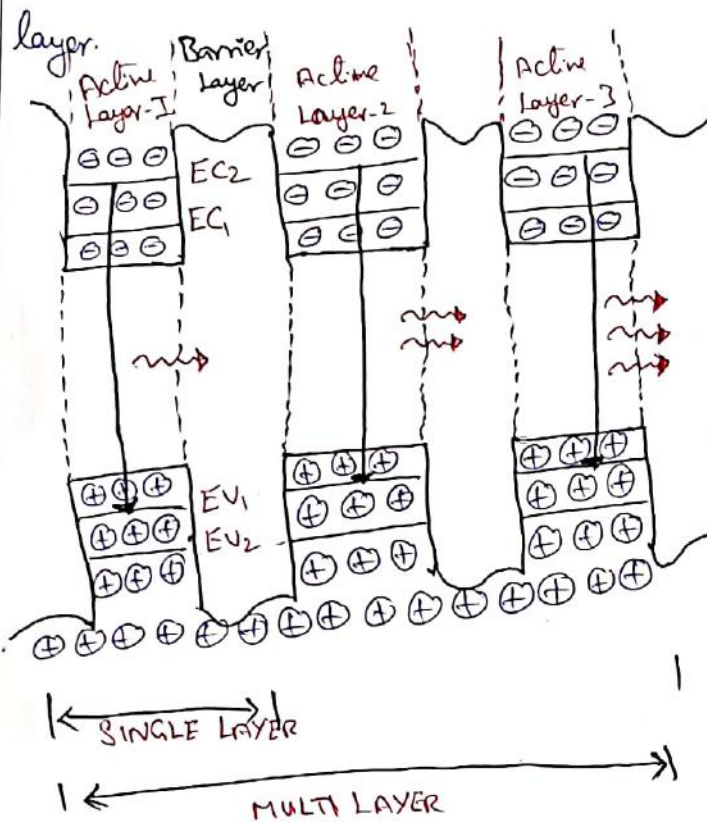
Construction:-

- ⊕ Single quantum well laser consist of a single active layer with different active energy level.
- ⊕ Many single quantum well are coupled together to form multi quantum well laser.

There are two type of quantum well laser,
 i) Single Quantum Well Laser.
 ii) Multi Quantum well Laser.



⊗ In multi quantum well laser, the active layer are separated by the barrier layer.



Working:-

⊗ Both single and multilayer quantum well laser, the recombination between the conduction and valence band energy level.

⊗ The electron from the conduction band energy level EC_2 recombine with the hole in the valence band energy level EV_1 .

⊗ In multi layer quantum well laser, the photon emitted from active layer multiplies in the second active layer and further multiplies in other layer and so on.

⊗ Hence, in multi-layer quantum well laser, the efficiency is more than the single layer of quantum well laser.

Advantages:-

- ➔ It has higher efficiency
- ➔ It produces higher modulation bandwidth.
- ➔ It have dynamic spectral width, lower threshold current

Application:

- ⊗ It is used for material processing
- ⊗ It is also employed in Laser Printing.
- ⊗ It is used in medical field such as Laser Scanning, medical therapy etc.
- ⊗ Single frequency source for telecommunication shall also be obtained using Quantum well laser.

BALLISTIC TRANSPORT:-

Def: When mean free path of the electron is longer than the dimension of the medium through which the electron travels is called "Ballistic Transport".

Explanation:-

When the length 'L' of the conductor become much smaller than the

Mean free path ' L_m ' the transport is termed 'Ballistic', that the electron do not scatter during the time it takes to travel through the conductor.

For example, ballistic transport can be observed in a metal nanowire.

Condition of Ballistic Transport:-

The mean free path can be increased by reducing the number of impurities in a crystal or by lowering its temperature.

- i) $L \ll L_m$
ii) $L \ll L_d$

Where

$L \Rightarrow$ Length of the conductor

$L_m \Rightarrow$ Mean free path.

$L_d \Rightarrow$ Length over an electron travel before inelastic collision.

The electron doesn't hit anything as it travel through the material, there is no momentum or phase relaxation.

Application:

Ballistic transport is to ultra short-channel semiconducting FETs or Carbon nano tube transistors.

QUANTUM CONFINEMENT :-

It is a process of reducing the size of a cubic solid, so that the energy level inside become discrete.

⊗ It is observed when the size of the particle is too small compare to the wavelength of the electron.

⊗ In which only small percent of electron free to move during confinement.

⊗ By bottom up or Top down process the dimension reduced.

QUANTUM STRUCTURE :-

When a bulk material reduced in its size. If the reduced dimension is in the order of few nanometers, then the structure is known as "Quantum Structure".

It is classified into 3 types based on direction.

- i) Quantum well
- ii) Quantum Wire.
- iii) Quantum Dot.

i) Quantum Well :-

If one dimension is reduced to nano range while the other two dimension remain large, then we get a structure

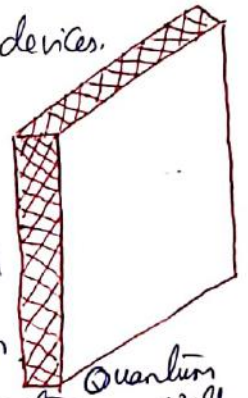
known as "Quantum well".

⊗ Quantum well are made from alternative layer of different semiconductor or by deposition of very thin metal film.

⊗ It is a large structure in which the carrier particles are free to move in 2D.

⊗ The particles are confined in one dimension, they are considered as Quantum Confinement.

⊗ Confinement of carriers, the quantum well structure has important application to making devices.

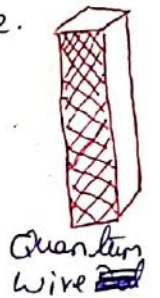


ii) Quantum Wire :-

⊗ If 2D are reduced and one dimension remain large, the resulting structure, "Quantum Wire".

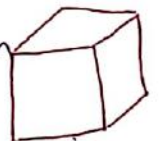
⊗ The carriers are free to move its trajectory along the wire.

⊗ Quantum wire structure are nanowire, nanorod and nanotube.



iii) Quantum Dots :-

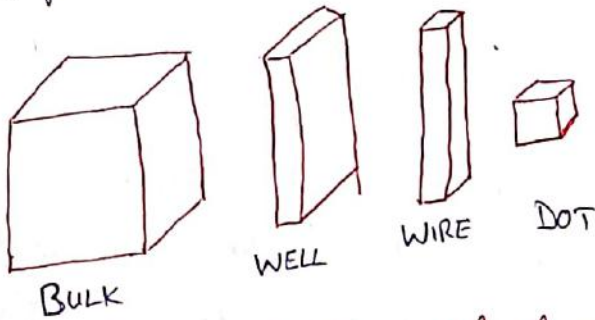
⊗ All three dimension are minimized, the resulting structure is known as "Quantum Dot".



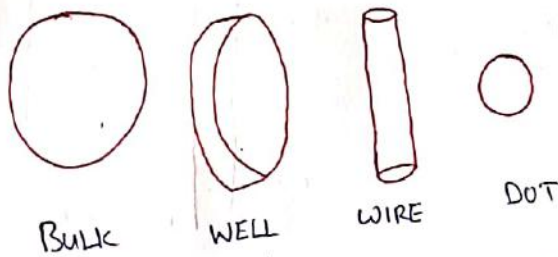
⊗ The Carriers has only Confined state is not freely moving.

⊗ It has many thousand of atom, Carrier are considered a single atom due to its peculiar properties.

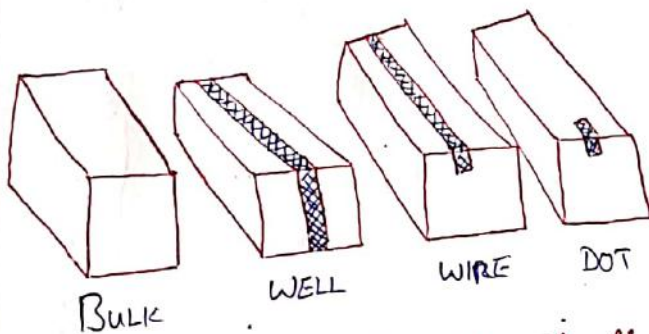
⊗ It is used in a quantum computer and quantum dot laser etc



"Rectangular Nano Structure"



"Curvilinear Nano Structure"



"Three Quantum Structure"

DENSITY OF STATE IN QUANTUM

WELL, QUANTUM WIRE & QUANTUM DOT:

Bulk Structure:

Density of state } $Z(E) = \frac{8\pi V Z m^*{}^{3/2} (E - E_c)^{1/2}}{h^3}$

$E_c \Rightarrow$ Bottom of Conduction Band Energy

$m^* \Rightarrow$ Effective Mass of electron.

Quantum Well:

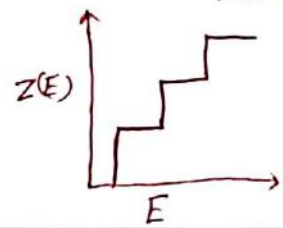
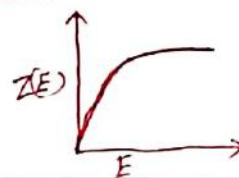
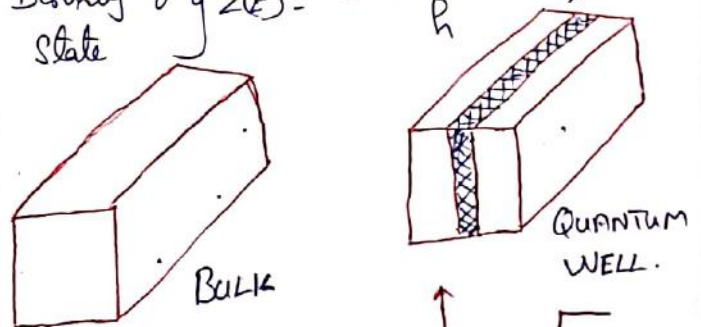
⊗ The electron can move freely in two dimension and Confined in only one direction.

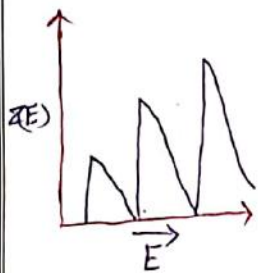
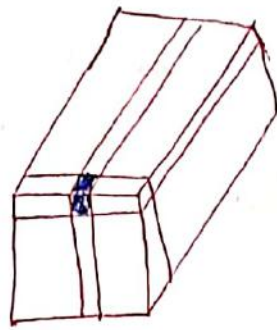
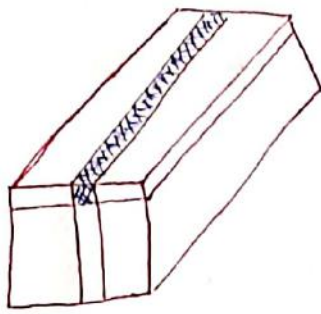
Density of state } $Z(E) = \frac{4\pi m^*}{h^2} E_0 > E_i ;$
 $i = 1, 2, 3.$

Quantum Wire:

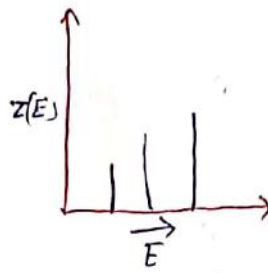
⊗ It provide only one non-confinement direction, it can move only one direction; the remaining two direction are Confined for charge carrier.

Density of state } $Z(E) = \frac{2\sqrt{2} m^* (E - E_i)^{-1/2}}{h} ; i = 1, 2, 2.$





QUANTUM WIRE



QUANTUM DOT.

SINGLE ELECTRON TRANSISTOR (SET)

⊗ SET is three-terminal switching device which can transfer electron from source to drain one by one.

⊗ SET is individually control the tunneling of electron into and out of the quantum dot.

Construction & Working:

⊗ Apply voltage bias to the gate voltage; voltage difference occurs between source & drain. That the current and electron flow in the same direction, from which the electron are originate.

⊗ Gate voltage create an electric field that alter the conductivity of the semiconducting channel below it, enabling current to flow from source to drain.

⊗ Due to electric field, change in potential energy in dot w.r.t to source and drain.

⊗ Gate voltage-controlled potential difference make electron in the source attracted to the dot, simultaneously electron in the dot attracted to the drain.

Energy need to move a charge Q , across the potential difference ' V '.

$$E = VQ$$

$$V = \frac{E}{Q} = \frac{E}{e} = \frac{W_c}{e}$$

$\therefore Q \Rightarrow$ charge of electron, ' e '

$W_c \Rightarrow$ charging energy.

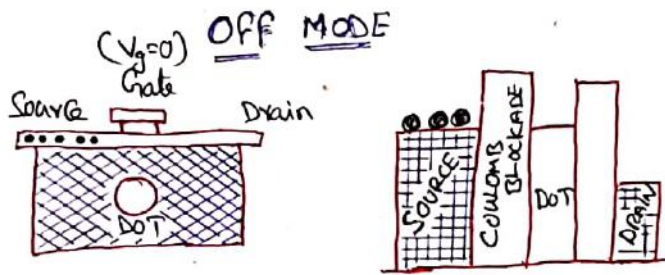
$$V = \frac{e}{2C}$$

$$\therefore W_c = \frac{e^2}{2C}$$

This much of voltage require to electron tunnel through Coulomb blockade of quantum dot.

Working:

The SET has an electrically isolated quantum dot located between the source & drain.



⊗ SET in "ON" mode, electron tunnel one at a time via the dot from source to drain.

⊗ Apply proper gate voltage, the potential energy of dot is low to encourage electron to tunnel through energy barrier.

⊗ The electron is on it, the dot potential energy rises as in fig.

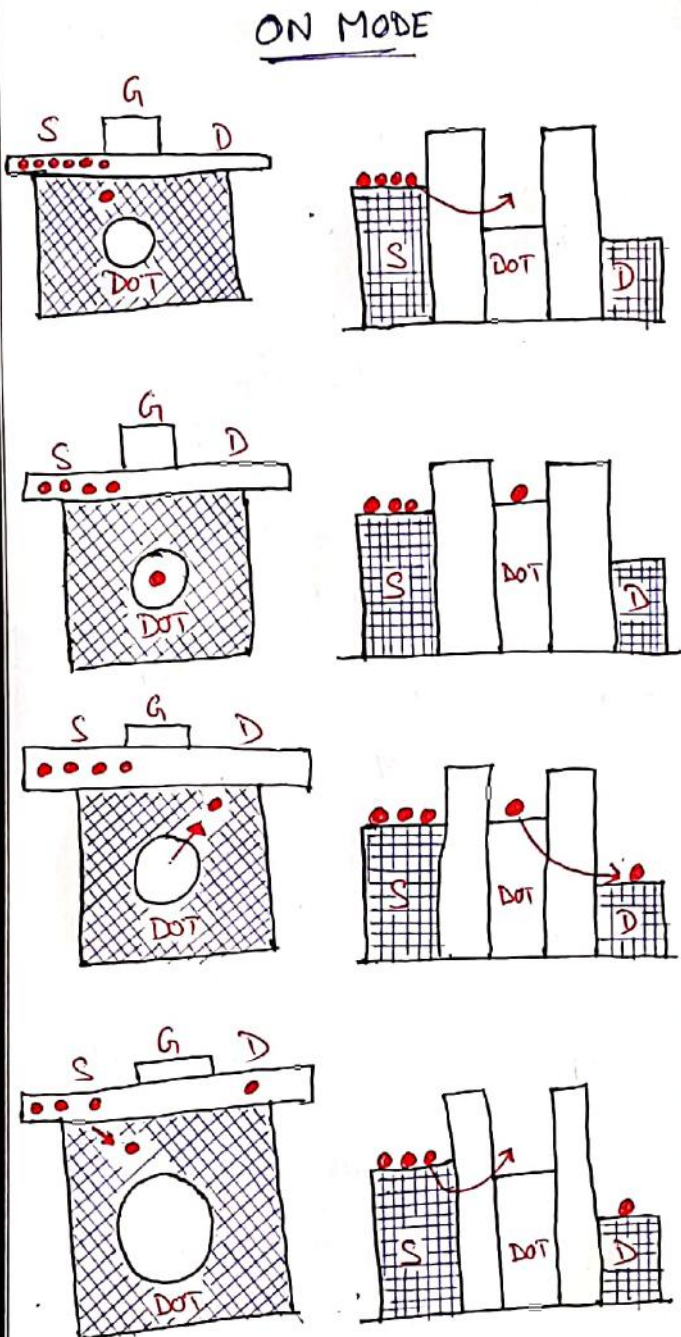
⊗ Electron then tunnel through the Coulomb blockade on the other side to reach the lower potential energy at the drain.

⊗ The dot empty and the potential lower again, the process repeats.

Application:-

- SET is used in sensor technology and digital electronic circuits
- It is used for mass data storage.
- It is used in highly sensitive electrometer
- SET is suitable measurement set-up for single electron spectroscopy.

⊗ SET in "OFF" mode, it is not energetically favorable for electron source to dot via tunnel.



CARBON NANOTUBE:- [CNT]

The hexagonal lattice of Carbon is simply graphite. A single layer of graphite is called Graphene.

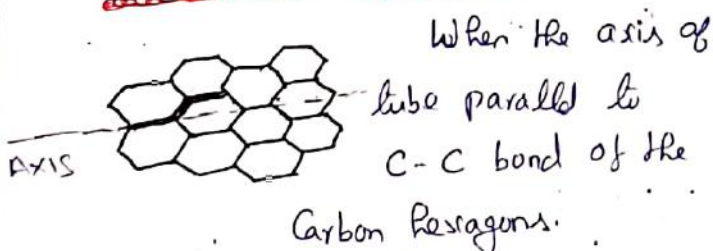
When the graphene layer is rolled, the structure is tube like and it is a single molecule, and is made up of a hexagonal network of covalently bonded Carbon atoms.

Type of CNT:-

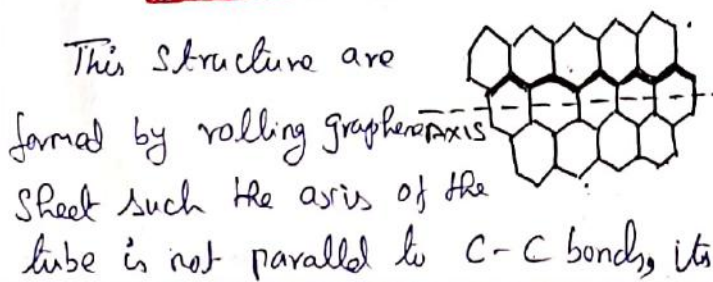
Three type of nanotube structure are considered by rolling a graphite sheet base on axis,

- i) Arm chair structure
- ii) Zig-Zag structure
- iii) Chiral structure.

i) Arm Chair Structure:-

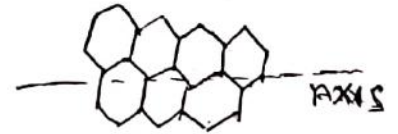


ii) Zig-Zag Structure:-



perpendicular to C-C bonds.

iii) Chiral Structure:-



In chiral structure, C-C bond is inclined towards the axis of the tube.

Properties of CNT:-

i) Electrical Properties:-

⊗ Carbon nanotube are metallic or semiconducting depending on the diameter or chirality.

⊗ Energy gap of semiconducting chiral carbon nanotube is inversely proportional to the diameter of the tube.

⊗ The energy gap also varies along the tube axis and reaches a minimum value at the tube end.

ii) Mechanical Properties:-

⊗ Structured based on aligned Carbon-Carbon bond will ultimately high strength:

⊗ One of the important properties of nanotube is ability to withstand extreme strain.

⊗ It have high ultimate tensile strength.

iii) Physical Properties:-

⊗ The surface area of nanotube is the order of $10-20 \text{ m}^2/\text{g}$ which is

Higher than graphite.

iv) Chemical Properties:-

It is difficult to oxidize them and the onset of oxidation in nanotube is 100°C higher than that of carbon fibres.

As a result, temperature is not a limitation in practical application of nanotubes.

v) Thermal Properties:

It has a high thermal conductivity and the value increases with decrease in diameter.

Application:

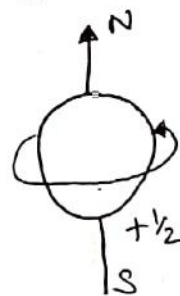
- ⊗ It is used in development of flat panel display.
- ⊗ It is used to make a computer switching devices.
- ⊗ It can be used for storing the hydrogen, which is used in the development of fuel cell.
- ⊗ It can be used to increase the tensile strength of steel.
- ⊗ It acts as a catalyst for some chemical reactions.

SPINTRONICS:-

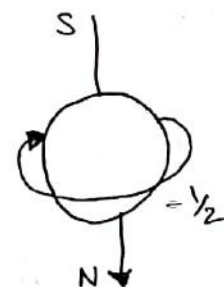
Spintronics is a nano technology which deals with spin dependent properties of an electron instead of charge dependent properties.

⊗ Spintronics is based on the spin of electron rather than its charge.

⊗ Electron exists in one of two states - Spin up and Spin down (or) clockwise and anticlockwise. Represented by '0' and '1'.



Spin up



Spin Down.

Explanation:-

Spinning of electron is like a tiny magnet with north and south poles. The orientation of north-south axis depends on the particle axis of spin.

For ordinary material, the magnetic moments cancel each other, but in ferromagnetic material, it

exhibits magnetic properties. This result in a permanent magnet.

Working:-

All spintronic devices act in simple scheme;

⊗ Information is stored into spin as a particular spin orientation (up or down).

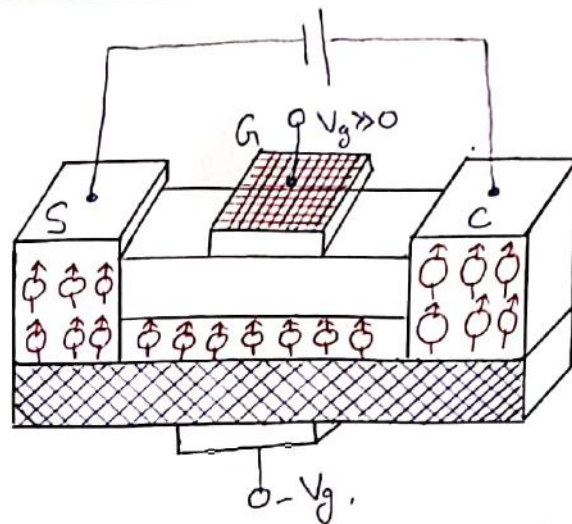
⊗ The spins, being attached to mobile electron, carry information along a wire and the information is read at a terminal.

⊗ Spin orientation of electron in spintronic device useful for memory storage and magnetic sensor application.

⊗ These are used for quantum computing, electron spin will represent a bit (qubit) of information. When electron spins are aligned this create a large scale net magnetic moment.

SPIN-FET:-

A Spin based Field Effect Transistor is SPIN-FET.



First the spins have to be injected from source into the non-magnetic layer and then transmitted to the collector.

The injected spin which are transmitted through this layer start precessing as in fig., before they reach the collector due to the spin-orbit coupling effect.

Hence, the net spin polarization is reduced. In order to solve this problem an electrical field is applied \perp to the plane of the film by depositing a gate electrode on the top to reduce the spin-orbit coupling effect.

If V_g is zero, net spin polarization are reduced before they

reach the collector.

If $V_g \gg 0$, the precession of electron is controlled by electric field to reach the collector with the same polarization.

By controlling the gate voltage and polarity, the current in the collector can be modulated just like the MOSFET of the conventional electronics.